

UTILITY PATENT APPLICATION TRANSMITTAL
(Large Entity)

(Only for new nonprovisional applications under 37 CFR 1.53(b))

Docket No.
13322(YOR92000-0036US1)

Total Pages in this Submission
3

TO THE ASSISTANT COMMISSIONER FOR PATENTS

Box Patent Application
Washington, D.C. 20231

Transmitted herewith for filing under 35 U.S.C. 111(a) and 37 C.F.R. 1.53(b) is a new utility patent application for an invention entitled:

PRECURSOR SOURCE MIXTURES, METHODS OF FILM DEPOSITIONS, AND FABRICATION OF STRUCTURES

and invented by:

Douglas A. Buchanan
Deborah Ann Neumayer

jc675 U S P T O
09/553997
04/20/00



If a **CONTINUATION APPLICATION**, check appropriate box and supply the requisite information:

Continuation Divisional Continuation-in-part (CIP) of prior application No.: _____

Which is a:

Continuation Divisional Continuation-in-part (CIP) of prior application No.: _____

Which is a:

Continuation Divisional Continuation-in-part (CIP) of prior application No.: _____

Enclosed are:

Application Elements

1. Filing fee as calculated and transmitted as described below

2. Specification having 87 pages and including the following:
 - a. Descriptive Title of the Invention
 - b. Cross References to Related Applications (*if applicable*)
 - c. Statement Regarding Federally-sponsored Research/Development (*if applicable*)
 - d. Reference to Microfiche Appendix (*if applicable*)
 - e. Background of the Invention
 - f. Brief Summary of the Invention
 - g. Brief Description of the Drawings (*if drawings filed*)
 - h. Detailed Description
 - i. Claim(s) as Classified Below
 - j. Abstract of the Disclosure

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Application Elements (Continued)

3. Drawing(s) (*when necessary as prescribed by 35 USC 113*)
 - a. Formal Number of Sheets 11
 - b. Informal Number of Sheets _____
4. Oath or Declaration
 - a. Newly executed (*original or copy*) Unexecuted
 - b. Copy from a prior application (37 CFR 1.63(d)) (*for continuation/divisional application only*)
 - c. With Power of Attorney Without Power of Attorney
 - d. **DELETION OF INVENTOR(S)**
Signed statement attached deleting inventor(s) named in the prior application,
see 37 C.F.R. 1.63(d)(2) and 1.33(b).
5. Incorporation By Reference (*usable if Box 4b is checked*)
The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied under Box 4b, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.
6. Computer Program in Microfiche (*Appendix*)
7. Nucleotide and/or Amino Acid Sequence Submission (*if applicable, all must be included*)
 - a. Paper Copy
 - b. Computer Readable Copy (*identical to computer copy*)
 - c. Statement Verifying Identical Paper and Computer Readable Copy

Accompanying Application Parts

8. Assignment Papers (*cover sheet & document(s)*)
9. 37 CFR 3.73(B) Statement (*when there is an assignee*)
10. English Translation Document (*if applicable*)
11. Information Disclosure Statement/PTO-1449 Copies of IDS Citations
12. Preliminary Amendment
13. Acknowledgment postcard
14. Certificate of Mailing
 First Class Express Mail (*Specify Label No.:*) EL357933039US

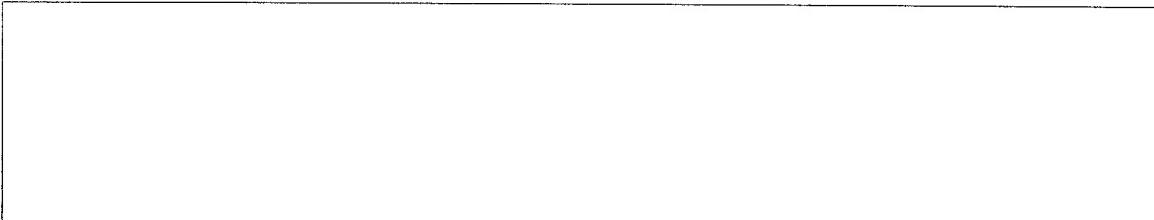
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Accompanying Application Parts (Continued)

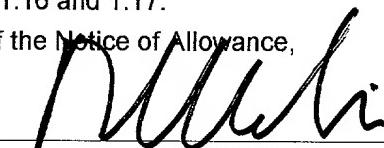
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16. Additional Enclosures (*please identify below*):


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Indep. Claims	1	- 3 =	0	x \$78.00	\$0.00
Multiple Dependent Claims (check if applicable)	<input checked="" type="checkbox"/>				\$260.00
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				TOTAL FILING FEE	\$1,710.00

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Signature

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Dated: April 20, 2000

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Applicant(s): Douglas A. Buchanan, et al.

Docket No.

13322(YOR92000-0036US1)

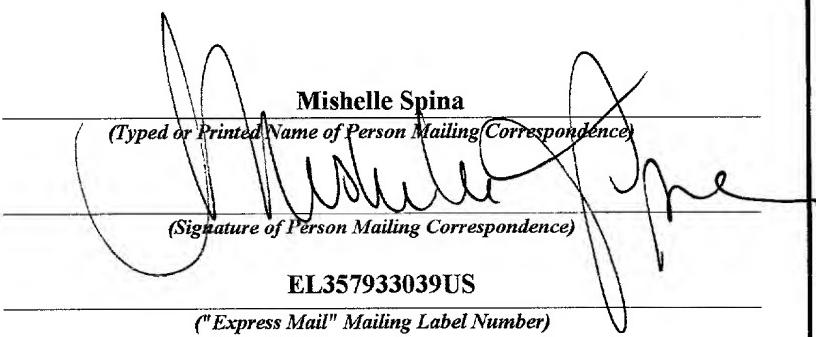
Serial No.
UnassignedFiling Date
HerewithExaminer
UnassignedGroup Art Unit
Unassigned**Invention: PRECURSOR SOURCE MIXTURES, METHODS OF FILM DEPOSITIONS, AND FABRICATION OF STRUCTURES**JC675 U.S. PTO
09/553997
04/20/00
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on April 20, 2000

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PRECURSOR SOURCE MIXTURES, METHODS OF FILM
DEPOSITION, AND FABRICATION OF STRUCTURES

DESCRIPTION

5

Field of the Invention

The present invention relates to deposition methods, and
more particular to a precursor source mixture that is
10 useful in chemical vapor deposition (CVD) and atomic
layer deposition (ALD) processes. The present invention
is also directed to a method of fabricating electronic
devices that contain at least a film, layer or coating
deposited from the precursor source mixture of the
15 present invention.

Background of the Invention

As dimensions of semiconductor devices shrink to improve
20 performance, the need to control film thickness to
thinner and thinner uniform dimensions increases.
Thickness uniformity is important as dimensions shrink to
minimize overlap with adjacent devices. Improvement in
uniformity is especially important in current
25 technologies utilizing shallow (0.25 micron) source/drain
diffusions. Because shallow diffusions can be obtained
by implanting through an oxide, any non-uniformity in
that oxide thickness would result in non-uniform
source/drain diffusion depths, degrading device
30 performance. Improved thickness uniformity is also
important during etching to minimize over-etching which
is directly dependent on film uniformity.

Most films deposited by CVD or ALD for semiconductor applications are grown using conventional bubbler technology with a carrier gas bubbled through a neat (i.e., without solvent) precursor at an elevated temperature, relying on the vapor pressure of the precursor to be constant in order to deliver a uniform precursor flux to the film. However, because vapor pressure is directly related to temperature, conventional bubbler technology suffers from the disadvantage of needing to maintain a bubbler temperature with minimal variation during a run or from run to run. Fluctuations in precursor flux are known to result in variable film growth rates. Solid compounds are known to sinter and change surface area over time, resulting in non-uniformity in film growth rates from run to run.

Sintering is not a problem for liquid precursors, but over time the liquid precursors may degrade from the thermal cycling and thermal load placed on the precursor. In addition, at elevated temperatures, decomposition processes are accelerated. Elevated temperatures and thermal cycling of a precursor during vaporization in a conventional bubbler may contribute to premature degradation of the precursor over time. Precursors may change their chemical state by ligand rearrangement, cluster formation, or oxidation. Precursors may react with water or oxygen inadvertently introduced into the bubbler through inadequately purified carrier gases bubbled through the precursor, air leaks, or water and oxygen adsorbed on the bubbler walls.

30

Examples of precursors which are typically used in conventional bubbler technology and suffer from the disadvantages listed above include hydrides, alkyls, alkenyls, cycloalkenyls, aryls, alkynes, carbonyls, amides, phosphides, nitrates, halides, alkoxides, siloxides, and silyls. Thermally unstable hydrides such as alkylamine alanes are especially attractive for CVD and ALD because their high reactivity usually translates into low thermal processing temperatures, and reduced impurity incorporation. Unfortunately, the alkylamine alanes are notoriously unstable during storage, transport and vaporization leading to poor reproducibility in the resultant films. Alkylamine alanes such as trimethylamine alan, triethylamine alan and diethylmethylamine alan are known to decompose at temperatures greater than 40°C during storage, and during transportation to the CVD reactor. Care must be taken to store the precursors at room temperature or less to minimize decomposition. Transport and vaporization temperatures are thus limited by the thermal decomposition of the precursor, See, for example, Dario M. Frigo, and Gerbrand J.M. van Eijden, Chemistry of Materials, 1994, 6, 190-195 and C.E. Chryssou and C.W. Pitt, Applied Physics A Materials Science and Processing, vol. 65, 1997, 469-475.

Another example of thermally unstable precursors are Cu(I) compounds such as (cyclopentadienyl)Cu(PEt₃) which is known to decompose with loss of PEt₃ at temperatures as low as 70°C. Other examples include alkyls such as trimethylindium and triethylindium. Triethylindium is a

liquid and is known to decompose at room temperature in the bubbler. Trimethylindium is a solid at room temperature and over time a change in the effective vapor pressure is observed resulting in undesirable non-uniformities and irreproducibility of growth results,
5 See, G.B. Stringfellow, Organometallic Vapor-Phase Epitaxy: Theory and Practice (San Diego, CA: Academic Press, 1989).

10 Other examples include alkoxides which are known to change their chemical state by ligand rearrangement, hydrolysis, oligomerization, ring formation, cluster formation, and/or oxidation over time. At the elevated temperatures encountered in conventional bubbler
15 technology, these decomposition processes are accelerated. In addition, alkoxides are particularly sensitive to water and oxygen impurities which may be inadvertently introduced into the bubbler through inadequately purified carrier gases bubbled through the precursor, air leaks, or water and oxygen adsorbed on the bubbler walls. Hydrolysis reactions can occur and these reactions are accelerated at elevated temperatures which are commonly encountered in conventional bubbler
20 technology. Alkoxides also may exist in a number of isomeric forms which interconvert over time resulting in a variable vapor pressure. For example, aluminum isopropoxide exists in a number of isomeric forms with slow interconversion rates between the isomers. The vapor pressures of these isomers vary widely, making it
25 difficult to control the deposition rate of Al_2O_3 grown from this compound using conventional bubbler technology,
30

See R.G. Gordon, K. Kramer, X. Liu, MRS Symp Proc. Vol. 446, 1997, p. 383.

Other examples include amides which behave similarly to
5 alkoxides, being prone to ligand rearrangement,
hydrolysis, oxidation, oligomerization, ring formation
and existing in several interconvertable isomeric forms
resulting in irreproducible vapor pressures over time.
10 Other examples include anhydrous metal nitrates such as
titanium nitrate, zirconium nitrate and gallium nitrate.
These complexes are air and water sensitive and are known
to decompose at temperatures around 100°C. The metal
15 oxo-nitrates such as $\text{VO}(\text{NO}_3)_3$ and $\text{CrO}_2(\text{NO}_3)_2$ are light
sensitive, in addition to being air and water sensitive,
and should be stored at 0°C. This is disclosed, for
example, in D.G. Colombo, D.C. Gilmer, V. G. Young, S. A.
Campbell and W. L. Gladfelter Chem. Vap. Dep. 1998, 4,
No. 6, 1998 P. 220.
20 The use of β -diketonate containing precursors dissolved
in solution for CVD growth has been described previously.
U.S. Patent Nos. 5,204,314, 5,225,561, 5,280,012,
5,453,494, and 5,919,522 disclose the growth of Ca, Sr,
or Ba containing films using a solution containing a Ca,
25 Sr, or Ba complex bound to at least one β -diketonate
ligand, or β -diketonate derivative. U.S. Patent No.
5,555,154 discloses the growth of PbZrTiO_3 by chemical
vapor deposition using a solution containing Pb, Zr and
Ti dipivaloylmethanates in tetrahydrofuran. U.S. Patent
30 Nos. 5,677,002 and 5,679,815 disclose the growth of
tantalum and niobium containing films using a solution of
Nb and Ta bound to a least one β -diketonate ligand or

β-diketonate derivative. U.S. Patent No. 5,698,022 teaches precursor composition useful for chemical vapor deposition of lanthanide metal/phosphorus oxide films, comprising a precursor compound comprised of a lanthanide metal β-diketonate and a phosphorus containing ligand in a solvent. U.S. Patent No. 5,783,716 teaches the growth of Pt by CVD using a solution containing a Pt complex bound to a least one β-diketonate ligand, or β-diketonate derivative. U.S. Patent No. 5,820,664 teaches a metal source reagent liquid solution useful for chemical vapor deposition comprising a metal coordination complex including a metal coordinatively bound to a least one β-diketonate ligand or β-diketonate derivative. U.S. Patent No. 5,900,279 teaches a solution comprised of a β-diketonate containing precursors dissolved in one of the ligands of the complex. U.S. Patent No. 5,916,359 discloses the growth of $\text{SrBi}_2\text{Ta}_2\text{O}_9$ by CVD using a precursor composition consisting of Sr, Bi, Ta β-diketonate containing precursors dissolved in a three component solution of two different $\text{C}_6\text{-}\text{C}_{12}$ alkanes and a glyme-based solvent or polyamine. U.S. Patent No. 5,980,983 teaches the use of a mixture of metal β-diketonates for deposition of a metal-containing film. Despite the numerous disclosures of β-diketonate precursors, β-diketonate-containing precursors are known to have complex decomposition pathways which can lead to incorporation of substantial quantities of carbon or other unwanted impurities into the resultant films.

U.S. Patent No. 5,900,279 teaches a solution useful for CVD comprised of a metallic organic compound added to a liquid which consists essentially of a ligand of the

metallic organic compound. For example, dissolving a M(β -diketonate) in the β -diketone. This reference suffers from the disadvantage of having a huge excess of ligand present during decomposition of the precursor to form the film. The ligand solvent is prone to the same decomposition pathways as the precursor and the precursor decomposition fragments and thus may hinder decomposition of the precursor in the gas phase or on the film surface. Gas phase reactions between the vaporized precursor and partially decomposed precursor and the vaporized ligand solvent and its decomposition by-products are likely and may result in reduced volatility of the precursor, particulate formation in the vaporizer and reactor, and consequently, irreproducible growth rates.

In view of the drawbacks with prior art deposition processes, there is a continued need for developing deposition processes wherein new and improved precursor source mixtures are used for forming thinly deposited layers or films that can be used in various electronic devices.

Summary of the Invention

The present invention is directed to a precursor source mixture useful for CVD and ALD applications, methods of growing films (as well as layers, coatings and multilayers) utilizing the precursor source mixture of the present invention, and methods of fabricating electronic devices incorporating a film deposited by the inventive method. Suitable electronic devices that can be

fabricated in the present invention include, but are not limited to: transistors, capacitors, diodes, resistors, switches, light emitting diodes, lasers, wiring structures, interconnect structures or any other structure wherein the film of the present invention can be incorporated therein.

Specifically, the precursor source mixture of the present invention comprises at least one precursor composed of an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi, to which is bound at least one ligand selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and halogenated, sulfonated or silylated derivatives thereof, which is dissolved, emulsified or suspended in an inert liquid selected from the group consisting of aliphatic hydrocarbons, aromatic hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkynitrile, halogenated hydrocarbons, silylated hydrocarbons, thioethers, amines, cyanates, isocyanates, thiocyanates, silicone oils, nitroalkyl, alkynitrate, and mixtures thereof. The precursor source mixture may be a solution, emulsion or suspension and may consist of a mixture of solid, liquid and gas phases which are distributed throughout the mixture.

The present invention also relates to a CVD or ALD method of growing a film on a substrate utilizing the precursor source mixture of the present invention. The method of forming the film comprises vaporizing the precursor in the precursor source mixture, and depositing a constituent of the vaporized precursor on a substrate to form a film. In this aspect, the inert liquid, may or may not be co-vaporized with the precursor. In one embodiment, the inert liquid is vaporized with the precursor. In an alternative embodiment of the present invention, the inert liquid is not vaporized and is diverted from the reactor in liquid form.

Another aspect of the present invention relates to the fabrication of multilayer structures incorporating one or more layers deposited by the inventive method.

A still further aspect of the present invention relates to the fabrication of multicomponent films where at least one component is derived from a precursor source mixture of the present invention.

Further aspects of the present invention include:

- Fabricating an electronic structure incorporating a film deposited by the inventive method.
- Fabricating a complimentary metal oxide semiconductor (CMOS) integrated circuit logic device which contains both n-type field effect transistors (NFET) and p-type field effect transistors (PFET) formed on a single

substrate incorporating a film deposited by the inventive method, as shown in Figure 1.

-Fabricating an integrated circuit capacitor
5 incorporating a film deposited by the inventive method, as shown in Fig. 2.

-Fabricating an integrated circuit wiring structure
10 incorporating a film deposited by the inventive method, as shown in Fig. 3b

Brief Description of the Drawings

15 FIG. 1 is an illustration of a cross-sectional view of a integrated circuit with both PFET and NFET devices on a single substrate.

20 FIG. 2 is an illustration of a cross-sectional view of an integrated circuit capacitor.

FIGS. 3a-3b are illustrations of a cross-sectional view
25 of an integrated circuit wiring structure.

FIG. 4 is an illustration of a cross-sectional view of a
25 transistor.

FIGS. 5-12 are illustrations of a cross-sectional view of
the fabrication of a transistor.

30 FIG. 13 is an illustration of a cross-sectional view of a
transistor.

FIGS. 14-23 are illustrations of a cross-sectional view of the fabrication of a transistor.

5 FIGS. 24-28 are illustrations of a cross-sectional view of the fabrication of a stack capacitor.

10 FIG. 29 is a schematic representation of a delivery system for chemical vapor deposition or atomic layer deposition of a film or coating.

15 FIG. 30 is an illustration of a cross-sectional view of a trench capacitor.

Detailed Description of the Invention

15 As is stated above, the present invention relates to a precursor source mixture useful for CVD or ALD comprising (i) at least one precursor of the present invention and (ii) an inert liquid.

20 The precursor is defined as any compound which contains an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi, to which is bound at least one ligand selected from the group consisting of hydride (H), alkyl (CR_3), alkenyl ($CRCR_2$), cycloalkenyl, aryl, alkyne (CCR), carbonyl (CO), amido (NR_2), imido (NR), hydrazido ($NRNR_2$), phosphido (PR_2), nitrosyl (NO), nitryl (NO_2), nitrate (NO_3), nitrile (RCN), isonitrile (RNC), halide (F, Cl, Br, or I), azide (N_3), alkoxy (OR), siloxy ($OSiR_3$)

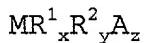
silyl (SiR_3), and halogenated, sulfonated or silylated derivatives thereof and when delivered to a vaporizer the precursor is readily converted into gaseous form.

5 Halogenated derivatives of the ligands are defined as replacement of H substituent(s) with a halogen selected from the group consisting of F, Cl, Br and I. Sulfonated derivatives of the ligands are defined as replacement of O substituent(s) with S. Silylated derivatives of the ligands are defined as replacement of C substituent(s)

10 with Si.

A generalized formula for the precursor of the present invention is

15



where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi; R^1 and R^2 are the same or different ligands selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and halogenated, sulfonated or silylated derivatives thereof; A is an optional coordinatively bound or associated ligand selected from the group consisting of phosphines (R_3P), phosphites ($(\text{RO})_3\text{P}$), amines (R_3N), arsines (R_3As), stibenes (R_3Sb), ethers (R_2O), sulfides (R_2S), nitriles (RCN), isonitriles (RNC), alkenes, hydrazine, pyridines, nitrogen heterocycles,

macrocycles, schiff bases, cycloalkenes, alcohols (ROH), phosphine oxides (R_3PO), alkylidenes, nitrites, alkynes, and water; $x \geq 1$; $x+y =$ the valence of the element M; $y \geq 0$; and z is ≥ 0 .

5

The preferred precursors of the present invention are compounds which are readily vaporized. Specifically, the preferred precursors are dimethyl-, diethyl-, or diisobutyl-B, Al, Ga, In, As, or Sb hydride;

- 10 $Me_2AlH(NEtMe_2)$; tertbutylarsine; $(Me_3N)AlH_3$; $(EtMe_2N)AlH_3$; $(Et_3N)AlH_3$; $CpWH_2$; Cp_2MoH_2 ; trimethyl-, triethyl-, triisobutyl-, tri-n-propyl-, triisopropyl-, tri-n-butyl-, tri-neopentyl-, or ethyldimethyl-B, Al, Ga, In, As or Sb; tetramethyl-, tetraethyl-, tetraphenyl-, or tetra-n-butyl-Si, Ge, Sn, or Pb; dimethyl-, diethyl-, or diisobutyl-B, Al, Ga, In, As or Sb hydride, chloride, fluoride, bromide, iodide, Cp, amide, dimethylamide or azide; triethyl-, triisobutyl-, tri-n-propyl-, triisopropyl-, tri-n-butyl- or ethyldimethyl-B, Al, Ga, In, As or Sb trimethylamine, diethylmethylamine, dimethylethylamine, or triethylamine; dimethyl or diethyl Zn, Cd, or Hg; $(neopentyl)_4Cr$; $Et_3Pb(neopentoxy)$; Cp_2Me_2Zr ; $(MeNC)_2PtMe_2$; $CpIr(C_2H_4)_2$; bisCp-Co, Mo, Fe, Mn, Ni, Ru, V, Os, Mg or Cr; bisethylbenzene-, bisbenzene-Co, Mo or Cr; triphenyl-Bi, Sb, or As; trivinylboron; trisCp-Sc, Y, La, Ce, Pr, Nd, Sm, Eu, Gd, Tb, D, Ho, Er, Tm, Yb, or Lu; trisallyliridium; $CpCr(CO)_2$; Cp_2ZrMe_2 ; $CpCuPEt_3$; $EtCpCuPEt_3$; $CpIn$; $CpIr(cyclooctadiene)$; $CpPd(allyl)$; $CpGaMe_2$; $CpGaEt_2$; $(cyclohexadiene)FeCO_3$; $(cyclooctatetraene)FeCO_3$; ethylferrocene; $CpMn(CO)_3$; $(cycloheptatriene)Mo(CO)_3$; $NdCp_3$; $SmCp_3$; $ScCp_3$; $TbCp_3$; $TlCp$; $TmCp_3$; Cp_2WH_2 ; $(mesitylene)W(CO)_3$; $CpRe(CO)_3$;

CpRh(CO)₂; Ir(allyl)₃; Pt(allyl)₂; CpIr(cyclooctanedione);
[Ir(OMe)(cyclooctanedione)]₂;
Ru(cyclooctanedione)(allyl)₂; Ru₃CO₁₂; Fe(CO)₅; Co₂(CO)₈;
Ru(CO)₃ (1,3-cyclohexadiene); Os₃CO₁₂; Cr(CO)₆; CpCo(CO)₂;
5 Mn₂(CO)₁₀; CpMn(CO)₃; Mo(CO)₆; Ni(CO)₄; Re₂(CO)₁₀; CpRe(CO)₃;
CpRh(CO)₂; Ru₃(CO)₁₂; W(CO)₆; CpV(CO)₄; CF₃Co(CO)₄;
Pt(CO)₂(cyclooctanedione); Ir(CO)₂(cyclooctanedione);
(CO)₄Fe[P(OCH₃)₃]; (CO)₄Fe[N(CH₃)₃]; CoNO(CO)₃; butoxy,
OCH(CF₃)₂, OCMe₂(CF₃), OCMe(CF₃)₂, OSi(CH₃)₃, OC(CH₃)₃,
10 OC(SiMe₃)₃, or OC(CF₃)₃ Li, Na, K, Rb, Cs, Fr, Cu, Ag, Au,
Hg, or Tl; tetra-methoxy, tetra-ethoxy, tetra-isopropoxy,
tetra-butoxy, tetra n-butoxy, tetra isobutoxy, tetra
tertbutoxy, OCH(CF₃)₂, OCMe₂(CF₃), OCMe(CF₃)₂, OC(CH₃)₃,
OC(SiMe₃)₃, OC(CF₃)₃ or OSi(CH₃)₃ Si, Ge, Sn, Pb, Ti, Zr, or
15 Hf; VO(isopropoxy)₃, tri-isopropoxy, tri-sec-butoxy,
tri-n-butoxy, tri-iso-butoxy, tri-methoxy, tri-ethoxy,
(OCH(CF₃)₂)₃, (OCMe₂(CF₃))₃, (OCMe(CF₃)₂)₃, (OC(CH₃)₃)₃,
(OC(SiMe₃)₃)₃, (OC(CF₃)₃)₃, or OSi(CH₃)₃)₃, B, Al, Ga, In, P,
As, or Sb; Et₃Pb(isopropoxide); (tertbutoxy)CuPMe₃;
20 tetrakis(dimethylamino), tetrakis(diethylamino) Ti, Zr,
Hf, Si, Ge, Sn, or Pb; diethylaminodiethylarsine;
diethylaminoarsine dichloride; bisdimethylaminoarsine
chloride; Me₂Zn(triethylamine)₂;
diethylaminodimethylstannane; tris(dimethylamino)
25 phosphine; tris(dimethylamino) antimony;
tris(dimethylamino) arsine; tris(dimethylamino) stibine;
tris-bis(trimethylsilyl)erbium amide;
bis(dimethylamino)(trimethylethylethylenediamino)
aluminium; (CO)₄Fe[N(CH₃)₃]; Li, Na, or K N(SiMe₃),
30 pentadimethylaminotantalum; diethylaminodimethyltin;
hexadimethylaminoditungsten;
trisdimethylamino(trimethylethylenediamino)titanium;

- CpCu(triphenylphosphine); (tertbutoxy)CuPMe₃; Pt(PF₃)₄;
Ni(PF₃)₄; Cr(PF₃)₆; (Et₃P)₃Mo(CO)₃; Ir(PF₃)₄; Ti(NO₃)₄;
Zr(NO₃)₄; Hf(NO₃)₄; Si(CH₃)₃(NO₃); RuNO(NO₃)₃; gallium
nitrate; Sn(NO₃)₄; Co(NO₃)₃; VO(NO₃)₃; CrO₂(NO₃)₂; TiCl₄;
5 HfCl₄; ZrCl₄; InCl₂; ZnCl₂; AlCl₃; SiCl₄; GaCl₃;
SnCl₄; CoCl₃; dimethyl-, diethyl-, or diisobutyl-, Al, B,
Ge, Si, or As halide; N(SiMe₃)₂, Li, Na, or K; B(CH₂SiMe₃)₃;
{(Me₃Si)₂N}-B, Al, Ga or In; (Me₃SiCH₂)₄-Ti, Zr or Hf;
{(Me₃Si)₂N}₂-Zn, Cd or Hg; where Cp is cyclopentadienyl or
10 substituted cyclopentadienyl wherein replacement of H
substituent(s) with methyl, ethyl, isopropyl, n-butyl,
sec-butyl, tert-butyl, trimethylsilyl or other like
substituents is contemplated.
- 15 An inert liquid is defined as any liquid which does not decompose when in contact with the precursor of the present invention during storage and during vaporization of the precursor. More specifically, the inert liquid employed in the precursor source mixture is selected from the group consisting of aliphatic hydrocarbons, aromatic hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkynitrile, halogenated hydrocarbons, silylated hydrocarbons, thioethers, amines, cyanates, isocyanates, thiocyanates, silicone oils, nitroalkyl, alkynitrate and/or mixtures of one or more of the above. Preferably the inert liquid is composed essentially of a C₅-C₁₂ alkane. "Essentially composed of" is defined in the present invention as 70-100% by volume. An optional additive can be present provided that it
20 composes no more than 30% by volume of the inert liquid.
- 25
- 30

The selection of the inert liquid is based on the following criteria: of sufficient inertness not to decompose when in contact with the precursor or during volatilization of the precursor, to pass through the hot zone of the reactor without adversely adsorbing on the growing film surface resulting in incorporation of unwanted impurities in the resultant film.

10 The precursor source mixture of the present invention may be a solution, emulsion or suspension and may consist of a mixture of solid, liquid and gas phases which are distributed throughout the mixture.

15 The precursor source mixture of the present invention can be used in any CVD or ALD process with any delivery means currently employed. Thus, the invention is not limited to a specific CVD or ALD apparatus or to any delivery system. Chemical vapor deposition (CVD) is defined as introduction of multiple reagents into a reactor simultaneously. Atomic layer deposition (ALD) is defined as sequential introduction of multiple reagents into a reactor, including, but not limited to: atomic layer epitaxy, digital chemical vapor deposition, pulsed chemical vapor deposition and other like methods.

20
25 In accordance with the present invention, a film is formed on a substrate utilizing the precursor source mixture of the present invention in any CVD or ALD process. The film is formed by vaporizing the precursor in the precursor source mixture, and thereafter depositing a constituent of the vaporized precursor on the substrate. In this aspect, the inert liquid, may or

may not be co-vaporized with the precursor. In one embodiment of the present invention, the inert liquid is vaporized with the precursor. In an alternative embodiment, the inert liquid is not vaporized and is diverted from the reactor in liquid form.

In addition to forming a film, the precursor source mixture can be employed in the fabrication of multilayer structures incorporating one or more film layers of the 10 present invention, or in the fabrication of multicomponent films where at least one component is derived from a precursor source mixture of the inventive method.

The precursor source mixtures of the present invention 15 can also be used in the fabrication of a structure, i.e., electronic device structure, incorporating a film deposited by the inventive method. The term "electronic device structure" is used in the present invention to denote transistors, capacitors, diodes, resistors, 20 varistors, switches, light emitting diodes, lasers, wiring structures, and/or interconnect structures.

Moreover, the precursor source mixtures can be used in 25 fabricating a complimentary metal oxide semiconductor (CMOS) integrated circuit logic device. More specifically, the present invention relates to the fabrication of a CMOS integrated circuit containing both n-type field effect transistors (NFET) and p-type field 30 effect transistors (PFET) formed on a single substrate. As shown in Fig. 1, NFET device 11 is formed on a p-type conductivity region 13 of substrate 10 and contains a

gate electrode 14 formed on a gate dielectric 15 and a pair of n-type source/drain regions 16 formed on laterally opposite sides of gate electrode 14.

Similarly, PFET device 17 is formed on a n-type conductivity region 18 of substrate 10 and contains the gate electrode 19 formed on gate dielectric 15 and a pair of p-type conductivity source/drain regions 20 formed along opposite sidewalls of gate electrode 19. The NFET and PFET devices are separated by shallow trench isolation 21 and by spacers 22. In this aspect of the invention, at least one of the transistor components is deposited by the inventive method including gate electrode 14, gate electrode 19, and/or gate dielectric 15 and/or spacers 22.

The precursor source mixture of the present invention can also be used in fabricating an integrated circuit capacitor. As shown in Fig. 2, a typical capacitor is formed on a substrate 30, connected by a plug 31 to a transistor, with a barrier 32 and consists of a bottom electrode 33, a dielectric material 34 which may or may not be ferroelectric, and a top electrode 35. In this aspect of the invention, at least one of the capacitor components is deposited by the inventive method including plug 31, barrier 32, bottom electrode 33, a dielectric material 34 and/or top electrode 35. The capacitor may be stack or trench.

The precursor source mixture can also be used in fabricating a structure of an integrated circuit wiring structure. As shown in Fig. 3a, a typical wiring structure is formed by etching trenches 41 and vias 42

into a dielectric layer 43. Below dielectric layer 43 is a metal thin film wire 44 and a dielectric layer 45 of a wiring layer. In Fig. 3b, the trench and via are filled with a barrier material 46 and a wiring metal 47. In
5 this aspect of the invention, at least one of the wiring structure components is deposited by the inventive method including dielectric layers 43 and 45, metal thin film wire 44, barrier material 46 and/or wiring metal 47.

10 Barrier layers that conformally coat the etched features of a dual damascene structure can also be fabricating using the precursor source mixture of the present invention.

15 The above is a generic description of the present invention, the following description provides specific details of the present invention.

20 Precursor source mixtures for hydride-containing compounds

Preferred precursor source mixtures of hydride-containing compounds are comprised of:

25 (i) $MR^1_xR^2_yA_z$

where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb and Bi, preferably B, Al, Ga, In, As, Sb, Si, Ge, Sn, Pb, Zn, Cd and Hg; R^1 is a hydride; R^2 is a ligand selected
30

from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, 5 sulfonated or silylated derivatives thereof, R¹ and R² may or may not be identical ligands; A is an optional coordinatively bound ligand selected from the group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, 10 isonitriles, alkenes, alkynes, hydrazine, pyridines, nitrogen heterocycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, alkylidenes, nitrites, and water; x ≥ 1; y ≥ 0; z is ≥ 0; and x+y = the valence of element M.

15

(ii) inert liquid

wherein the inert liquid is selected from the group consisting of aliphatic hydrocarbons, aromatic 20 hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkynitrile, halogenated hydrocarbons, silylated hydrocarbons, thioethers, amines, cyanates, isocyanates, thiocyanates, silicone oils, nitroalkyl, alkynitrate and/or mixtures of one or more 25 of the above. Preferably, the inert liquid is composed essentially of a C₅-C₁₂ alkane.

(iii) optional additive

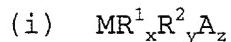
30 In the case of unstable hydride-containing compounds which have a tendency to decompose during storage or vaporization, additional non-hydride ligands may be added

to the mixture to improve the stability of the compound. In the case of unstable adducts of hydride-containing compounds, additional adducts may be added to the mixture to improve the stability of the compound. Other 5 coordinating compounds may be added to the mixture to improve stability of the compound as well including, but not limited to: phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, pyridines, heterocycles, 10 tetrahydrofuran, dimethylformamide, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, or alkynes. All optional additives will comprise no more than 30% by volume of the inert liquid.

15 Highly preferred precursor source mixtures comprised of at least one hydride-containing compound include, but not limited to: dimethyl-, diethyl-, or diisobutyl-B, Al, Ga, In, As, or Sb hydride; tertbutylarsine; CpWH₂ or Cp₂MoH₂ dissolved, emulsified or suspended in a liquid composed 20 essentially of a C₅-C₁₂ alkane liquid. Other preferred precursor source mixtures are comprised of at least one hydride-containing compound including, but not limited to: Me₂AlH(NEtMe₂) ; (Me₃N)AlH₃; (EtMe₂N)AlH₃ or (Et₃N)AlH₃ emulsified or suspended in a liquid composed essentially 25 of a C₅-C₁₂ alkane liquid with optionally added amine (no more than 30% by volume of the inert liquid).

Precursor Source mixtures for alkyl-containing compounds

30 Preferred precursor source mixtures of alkyl-containing compounds are comprised of:



where M is an element selected from the group consisting
5 of Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr,
Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag,
Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb
and Bi, preferably B, Al, Ga, In, As, Sb, Si, Ge, Sn, Pb,
10 Zn, Cd, Hg; R¹ is a C₁-C₈ alkyl, or C₄-C₁₂ cycloalkyl; R² is
a ligand selected from the group consisting of hydride,
alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl,
amido, imido, hydrazido, phosphido, nitrosyl, nitryl,
nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl,
15 and/or halogenated, sulfonated or silylated derivatives
thereof, R¹ and R² may or may not be identical ligands; A
is an optional coordinatively bound ligand selected from
the group consisting of phosphines, phosphites, aryls,
amines, arsines, stibenes, ethers, sulfides, nitriles,
20 isonitriles, alkenes, alkynes, hydrazine, pyridines,
nitrogen heterocycles, macrocycles, schiff bases,
cycloalkenes, alcohols, phosphine oxides, alkylidenes,
nitrites, and water; x ≥ 1; y ≥ 0; z is ≥ 0; and x+y =
the valence of element M.

25 (ii) inert liquid

wherein the inert liquid is selected from the group
consisting of aliphatic hydrocarbons, aromatic
hydrocarbons, alcohols, ethers, aldehydes, ketones,
30 acids, phenols, esters, amines, alkynitrile, halogenated
hydrocarbons, silylated hydrocarbons, thioethers, amines,
cyanates, isocyanates, thiocyanates, silicone oils,

nitroalkyl, alkynitrate and/or mixtures of one or more of the above. Preferably, the inert liquid is composed essentially of a C₅-C₁₂ alkane.

5

(iii) optional additive

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In the case of unstable alkyl-containing compounds which have a tendency to decompose during storage or vaporization, additional alkyl ligands may be added to the mixture to improve the stability of the compound. In the case of unstable adducts of alkyl-containing compounds, additional adducts may be added to the mixture to improve the stability of the compound. Other coordinating compounds may be added to the mixture to improve stability of the compound as well including, but not limited to: phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, pyridines, heterocycles, tetrahydrofuran, dimethylformamide, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, or alkynes. All optional additives will comprise no more than 30% by volume of the inert liquid.

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Highly preferred precursor source mixtures comprised of at least one alkyl-containing compound include: trimethyl-, triethyl-, triisobutyl-, tri-n-propyl-, triisopropyl-, tri-n-butyl-, trineopentyl-, or ethyldimethyl-B, Al, Ga, In, As or Sb; tetramethyl-, tetraethyl-, tetraphenyl-, or tetra-n-butyl-Si, Ge, Sn, or Pb; dimethyl-, diethyl-, or diisobutyl-B, Al, Ga, In, As or Sb, hydride, chloride, fluoride, bromide, iodide, Cp, amide, dimethylamide or azide; triethyl-,

triisobutyl-, tri-n-propyl-, triisopropyl-, tri-n-butyl- or ethyldimethyl-B, Al, Ga, In, As or Sb trimethylamine, diethylmethylamine, dimethylethylamine, or triethylamine; dimethyl- or diethyl-Zn, Cd, or Hg; (neopentyl)₄Cr; Et₃Pb(neopentoxy); Cp₂Me₂Zr; (MeNC)₂PtMe₂; or CpIr(C₂H₄)₂ where Cp is cyclopentadienyl or substituted cyclopentadienyl wherein replacement of H substituent(s) with methyl, ethyl, isopropyl, n-butyl, sec-butyl, tert-butyl, trimethylsilyl or other like substituents dissolved, emulsified or suspended in a C₅-C₁₂ alkane liquid. Other preferred precursor source mixtures are comprised of at least one alkyl-containing compound including, but not limited to: trimethyl or triethyl in emulsified or suspended in a liquid composed essentially of a C₅-C₁₂ alkane liquid with optionally added methane or ethane (no more than 30% by volume of the inert liquid).

Precursor Source mixtures for alkenyl-containing compounds

Preferred precursor source mixtures of alkenyl containing compounds are comprised of:

(i) MR_x¹R_y²A_z
where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi, preferably Bi, As, Cr, Zr,

Cu, Co, In, Ir, Fe, La, Mg, Mn, Mo, Ni, Os, Ru, Tl, or W; R¹ is a C₁-C₈ alkenyl, C₄-C₁₂ cycloalkenyl or C₅-C₁₂ aryl; R² is a ligand selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silylated derivatives thereof, R¹ and R² may or may not be identical ligands; A is an optional coordinatively bound ligand selected from the group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, alkynes, hydrazine, pyridines, nitrogen heterocycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, alkylidenes, nitrites, and water; x ≥ 1; y ≥ 0; z is ≥ 0; and x+y = the valence of element M.

(ii) inert liquid

wherein the inert liquid is selected from the group consisting of aliphatic hydrocarbons, aromatic hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkynitrile, halogenated hydrocarbons, silylated hydrocarbons, thioethers, amines, cyanates, isocyanates, thiocyanates, silicone oils, nitroalkyl, alkynitrate and/or mixtures of one or more of the above. Preferably the inert liquid is composed essentially of C₅-C₁₂ alkane.

(iii) optional additive

In the case of unstable alkenyl-containing compounds which have a tendency to decompose during storage or vaporization, additional alkenyl ligands may be added to the mixture to improve the stability of the compound. In 5 the case of unstable adducts of alkenyl-containing compounds, additional adducts may be added to the mixture to improve the stability of the compound. Other coordinating compounds may be added to the mixture to improve stability of the compound as well including, but 10 not limited to: phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, pyridines, heterocycles, tetrahydrofuran, dimethylformamide, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, or 15 alkynes. All optional additives will comprise no more than 30% by volume of the inert liquid.

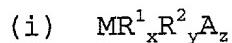
Highly preferred precursor source mixtures comprised of at least one alkenyl-containing compound selected from 20 the group consisting of bisCp Co, Mo, Fe, Mn, Ni, Ru, V, Os, Mg or Cr; bisethylbenzene, bisbenzene Co, Mo or Cr; triphenyl Bi, Sb, or As; trivinylboron, trisCp Sc, Y, La, Ce, Pr, Nd, Sm, Eu, Gd, Tb, D, Ho, Er, Tm, Yb, or Lu; tetraCpTh, Pa, V, Np, Pu or Am; trisallyliridium; 25 CpCr(CO)₂; Cp₂ZrMe₂; CpCuPEt₃; CpIn; CpIr(cyclooctadiene); CpPd(allyl); CpGaMe₂; CpGaEt₂; (cyclohexadiene)FeCO₃; (cyclooctatetraene)FeCO₃; ethylferrocene; CpMn(CO)₃; (cycloheptatriene) Mo(CO)₃; NdCp₃; SmCp₃; ScCp₃; TbCp₃; T1Cp; Cp₂WH₂; (mesitylene)W(CO)₃; CpRe(CO)₃; CpRh(CO)₂; 30 Ir(allyl)₃; Pt(allyl)₂; CpIr(cyclooctanedione); [Ir(OMe)(cyclooctanedione)]₂; or Ru(cyclooctanedione)(allyl)₂ where Cp is cyclopentadienyl

or substituted cyclopentadienyl wherein replacement of H substituent(s) with methyl, ethyl, isopropyl, n-butyl, sec-butyl, tert-butyl, trimethylsilyl or other like substituents dissolved, emulsified or suspended in C5-C12 alkane liquid.

5

Precursor Source mixtures for carbonyl-containing compounds

10 Preferred precursor source mixtures of carbonyl-containing compounds are comprised of:



15 where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi, preferably Ru, Fe, Co, Os, Cr, Mn, Mo, Ni, Re, Rh, W, Pt, or Ir; R¹ is a carbonyl; R² is a ligand selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silylated derivatives thereof, R¹ and R² may or may not be identical ligands; A is an optional coordinatively bound ligand selected from the group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, alkynes, hydrazine, pyridines, nitrogen heterocycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides,

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alkylidenes, nitrites, and water; $x \geq 1$; $y \geq 0$; z is ≥ 0 ; and $x+y =$ the valence of element M.

(ii) inert liquid

5

wherein the inert liquid is selected from the group consisting of aliphatic hydrocarbons, aromatic hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkynitrile, halogenated hydrocarbons, silylated hydrocarbons, thioethers, amines, cyanates, isocyanates, thiocyanates, silicone oils, nitroalkyl, alkynitrate and/or mixtures of one or more of the above. Preferably a liquid composed essentially of a C_5-C_{12} alkane.

10

(iii) optional additive

In the case of unstable carbonyl-containing compounds which have a tendency to decompose during storage or vaporization, additional non-carbonyl ligands may be added to the mixture to improve the stability of the compound. In the case of unstable adducts of carbonyl-containing compounds, additional adducts may be added to the mixture to improve the stability of the compound.

20

Other coordinating compounds may be added to the mixture to improve stability of the compound as well including, but not limited to: phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, pyridines, heterocycles, tetrahydrofuran, dimethylformamide, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, or

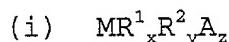
alkynes. All optional additives will comprise no more than 30% by volume of the inert liquid.

Highly preferred precursor source mixtures comprised of at least one carbonyl-containing precursor include:

Ru₃CO₁₂; Fe(CO)₅; Co₂(CO)₈; Ru(CO)₃ (1,3-cyclohexadiene); Os₃CO₁₂; Cr(CO)₆; CpCo(CO)₂; Mn₂(CO)₁₀; CpMn(CO)₃; (cycloheptatriene)Mo(CO)₃; Mo(CO)₆; Ni(CO)₄; Re₂(CO)₁₀; CpRe(CO)₃; CpRh(CO)₂; Ru₃(CO)₁₂; W(CO)₆; CpV(CO)₄; CF₃Co(CO)₄; Pt(CO)₂(cyclooctanedione); Ir(CO)₂(cyclooctanedione); (CO)₄Fe[P(OCH₃)₃]; (CO)₄Fe[N(CH₃)₃] or CoNO(CO)₃ where Cp is cyclopentadienyl or substituted cyclopentadienyl wherein replacement of H substituent(s) with methyl, ethyl, isopropyl, n-butyl, sec-butyl, tert-butyl, trimethylsilyl or other like substituents dissolved, emulsified or suspended in a C₅-C₁₂ alkane liquid.

Precursor source mixtures for alkoxy-containing compound

Preferred precursor source mixtures of alkoxy-containing compounds are comprised of:



where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi, preferably B, Al, Ga, In, As, Sb, Si, Ge, Ti, Zr, or Hf; R¹ is an alkoxy or siloxy;

R² is a ligand selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silylated derivatives thereof, R¹ and R² may or may not be identical ligands; A is an optional coordinatively bound ligand selected from the group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, alkynes, hydrazine, pyridines, nitrogen heterocycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, alkylidenes, nitrites, and water; x ≥ 1; y ≥ 0; z is ≥ 0; and x+y = the valence of element M.

15

(ii) inert liquid

where the inert liquid is selected from the group consisting of aliphatic hydrocarbons, aromatic hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkynitrile, halogenated hydrocarbons, silylated hydrocarbons, thioethers, amines, cyanates, isocyanates, thiocyanates, silicone oils, nitroalkyl, alkynitrate and/or mixtures of one or more of the above. Preferably a liquid composed essentially of C₅-C₁₂ alkane.

25

(iii) optional additive

30

In the case of unstable alkoxy-containing compounds which have a tendency to decompose or chemically rearrange during storage or vaporization, additional alkoxide

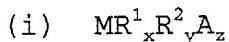
ligands may be added to the mixture to improve the stability of the compound. In the case of unstable adducts of alkoxy-containing compounds, additional adducts may be added to the mixture to improve the 5 stability of the compound. Other coordinating compounds may be added to the mixture to improve stability of the compound as well including, but not limited to: phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, 10 pyridines, heterocycles, tetrahydrofuran, dimethylformamide, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, or alkynes. All optional additives will comprise no more than 30% by volume of the inert liquid.

15 Highly preferred precursor source mixtures comprised of at least one alkoxy-containing precursor include: butoxy, $OCH(CF_3)_2$, $OCMe_2(CF_3)$, $OCMe(CF_3)_2$, $OSi(CH_3)_3$, $OC(CH_3)_3$, $OC(SiMe_3)_3$, or $OC(CF_3)_3$ Li, Na, K, Rb, Cs, Fr, 20 Cu, Ag, Au, Hg, or Tl; tetra-methoxy, tetra-ethoxy, tetra-isopropoxy, tetra-tert-butoxy, tetra-iso-butoxy, tetra-butoxy, tetra- $OCH(CF_3)_2$, tetra- $OCMe_2(CF_3)$, tetra- $OCMe(CF_3)_2$, tetra- $OC(CH_3)_3$, tetra- $OC(SiMe_3)_3$, tetra- $OC(CF_3)_3$, or tetra- $OSi(CH_3)_3$ Si, Ge, Sn, Pb, Ti, Zr, or Hf; 25 VO(isopropoxy)₃; tri-isopropoxy, tri-sec-butoxy, tri-n-butoxy, tri-iso-butoxy, tri-methoxy, tri-ethoxy, tri- $OCH(CF_3)_2$, tri- $OCMe_2(CF_3)$, tri- $OCMe(CF_3)_2$, tri- $OC(CH_3)_3$, tri- $OC(SiMe_3)_3$, tri- $OC(CF_3)_3$, or tri- $OSi(CH_3)_3$, B, Al, Ga, In, P, As, or Sb; Et₃Pb(isopropoxide), or 30 (tertbutoxy)CuPMe₃, dissolved, emulsified or suspended in a C₅-C₁₂ alkane liquid.

Precursor Source mixtures for amino-containing compound

Preferred precursor source mixtures of amino-containing compounds are comprised of:

5



where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi, preferably B, Al, Ga, In, As, Sb, Si, Ge, Sn, Pb, Zn, Cd, Hg, Ti, Zr, or Hf; R^1 is an amino; R^2 is a ligand selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido; imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silylated derivatives thereof, R^1 and R^2 may or may not be identical ligands, A is an optional coordinatively bound ligand selected from the group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, alkynes, hydrazine, pyridines, nitrogen heterocycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, alkylidenes, nitrites, and water; $x \geq 1$; $y \geq 0$; z is ≥ 0 ; and $x+y =$ the valence of element M.

30

(ii) inert liquid

wherein the inert liquid is selected from the group consisting of aliphatic hydrocarbons, aromatic hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkyl nitrile, halogenated hydrocarbons, silylated hydrocarbons, thioethers, amines, cyanates, isocyanates, thiocyanates, silicone oils, nitroalkyl, alkyl nitrate and/or mixtures of one or more of the above. Preferably a liquid composed essentially of a C₅-C₁₂ alkane.

10

(iii) optional additive

15

In the case of unstable amino-containing compounds which have a tendency to decompose or chemically rearrange during storage or vaporization, additional amino ligands may be added to the mixture to improve the stability of the compound. In the case of unstable adducts of amino-containing compounds, additional adducts may be added to the mixture to improve the stability of the compound.

20

Other coordinating compounds may be added to the mixture to improve stability of the compound as well including, but not limited to: phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, pyridines, heterocycles, tetrahydrofuran, dimethylformamide, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, or alkynes. All optional additives will comprise no more than 30% by volume of the inert liquid.

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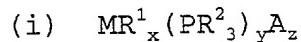
Highly preferred precursor source mixtures comprised of at least one amino-containing precursor include: tetrakis(dimethylamino), tetrakis(diethylamino) Ti, Zr,

Hf, Si, Ge, Sn, or Pb; diethylaminodiethylarsine;
diethylaminoarsine dichloride; bisdimethylaminoarsine
chloride; Me₂Zn(triethylamine)₂;
diethylaminodimethylstannane; tris(dimethylamino)
5 phosphine; tris(dimethylamino) antimony;
tris(dimethylamino) arsine; tris(dimethylamino) stibine;
tris-bis(trimethylsilyl) erbium amide;
bis(dimethylamino)(trimethylethylethylenediamino)
aluminium; (CO)₄Fe[N(CH₃)₃], Li, Na, or K N(SiMe₃);
10 pentadimethylaminotantalum; diethylaminodimethyltin;
hexadimethylaminoditungsten, or
trisdimethylamino(trimethylethylenediamino)titanium,
dissolved, emulsified or suspended in a C₅-C₁₂ alkane
liquid with additional amine.

15

Precursor Source mixtures for phosphido-containing
compound

20 Preferred precursor source mixtures of phosphido-
containing compounds are comprised of:



25 where M is an element selected from the group consisting
of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La,
V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni,
Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si,
Ge, Sn, Pb, As, P, Sb and Bi, preferably Cu, Ni, Pt, Ir,
30 Cr, or Mo; R¹ and R² are ligands selected from the group
consisting of hydride, alkyl, alkenyl, cycloalkenyl,
aryl, alkyne, carbonyl, amido, imido, hydrazido,

phosphido, nitrosyl, nitryl, nitrate, nitrile, halide,
azide, alkoxy, siloxy, silyl, and/or halogenated,
sulfonated or silylated derivatives thereof, R¹ and R² may
or may not be identical ligands; A is an optional
5 coordinatively bound ligand selected from the group
consisting of phosphines, phosphites, aryls, amines,
arsines, stibenes, ethers, sulfides, nitriles,
isocyanides, alkenes, alkynes, hydrazine, pyridines,
10 nitrogen heterocycles, macrocycles, schiff bases,
cycloalkenes, alcohols, phosphine oxides, alkylidenes,
nitrites, and water; x ≥ 1; y ≥ 0; z is ≥ 0; and x+y =
the valence of element M.

15 (ii) inert liquid

wherein the inert liquid is selected from the group
consisting of aliphatic hydrocarbons, aromatic
hydrocarbons, alcohols, ethers, aldehydes, ketones,
acids, phenols, esters, amines, alkynitrile, halogenated
20 hydrocarbons, silylated hydrocarbons, thioethers, amines,
cyanates, isocyanates, thiocyanates, silicone oils,
nitroalkyl, alkynitrile and/or mixtures of one or more
of the above. Preferably a liquid composed essentially
of a C₅-C₁₂ alkane.

25 (iii) optional additive

In the case of unstable phosphido-containing compounds
which have a tendency to decompose or chemically
30 rearrange during storage or vaporization, additional
phosphido ligands may be added to the mixture to improve
the stability of the compound. In the case of unstable

adducts of phosphido-containing compounds, additional adducts may be added to the mixture to improve the stability of the compound. Other coordinating compounds may be added to the mixture to improve stability of the compound as well including, but not limited to:
5 phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfdes, nitriles, isonitriles, alkenes, pyridines, heterocycles, tetrahydrofuran, dimethylformamide, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, or alkynes.
10 All optional additives will comprise no more than 30% by volume of the inert liquid.

Preferred precursor source mixtures are comprised of
15 CpCu(PEt₃); CpCu(triphenylphospine); (tertbutoxy)CuPMe₃; Pt(PF₃)₄; Ni(PF₃)₄; Cr(PF₃)₆; (Et₃P)₃Mo(CO)₃; or Ir(PF₃)₄ where Cp is cyclopentadienyl or substituted cyclopentadienyl wherein replacement of H substituent(s) with methyl, ethyl, isopropyl, n-butyl, sec-butyl, 20 tert-butyl, trimethylsilyl or other like substituents dissolved, emulsified or suspended in a C₅-C₁₂ alkane liquid with excess of phosphine.

25 Precursor Source mixtures for nitrate-containing compound

Preferred precursor source mixtures of nitrate-containing compounds are comprised of:

30 (i) MR_x¹R_y²A_z

where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi, preferably Ti, Zr, Hf, Si, Ga, Sn, Co, V, or Cr; R¹ is a nitrate; R² is a ligand selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silylated derivatives thereof, R¹ and R² may or may not be identical ligands; A is an optional coordinatively bound ligand selected from the group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, alkynes, hydrazine, pyridines, nitrogen heterocycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, alkylidenes, nitrites, and water; x ≥ 1; y ≥ 0; z is ≥ 0; and x+y = the valence of element M.

(ii) inert liquid

wherein the inert liquid is selected from the group consisting of aliphatic hydrocarbons, aromatic hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkynitrile, halogenated hydrocarbons, silylated hydrocarbons, thioethers, amines, cyanates, isocyanates, thiocyanates, silicone oils, nitroalkyl, alkynitrate and/or mixtures of one or more of the above. Preferably a liquid composed essentially of a C₅-C₁₂ alkane.

(iii) optional additive

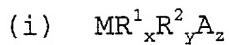
In the case of unstable nitrate-containing compounds which have a tendency to decompose or chemically rearrange during storage or vaporization, additional ligands may be added to the mixture to improve the stability of the compound. In the case of unstable adducts of nitrate-containing compounds, additional adducts may be added to the mixture to improve the stability of the compound.

Other coordinating compounds may be added to the mixture to improve stability of the compound as well including, but not limited to: phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfdes, nitriles, isonitriles, alkenes, pyridines, heterocycles, tetrahydrofuran, dimethylformamide, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, or alkynes. All optional additives will comprise no more than 30% by volume of the inert liquid.

Preferred precursor source mixtures are comprised of $Ti(NO_3)_4$; $Zr(NO_3)_4$; $Hf(NO_3)_4$; $Si(CH_3)_3(NO_3)$; $RuNO(NO_3)_3$; gallium nitrate; $Sn(NO_3)_4$; $Co(NO_3)_3$; $VO(NO_3)_3$; or $CrO_2(NO_3)_2$ dissolved, emulsified or suspended in a C_5-C_{12} alkane liquid.

Precursor Source mixtures for halide-containing compounds

Preferred precursor source mixtures of halide-containing compounds are comprised of:



where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi, preferably Ti, Zr, Hf, Si, Ga, Sn, Co, V, or Cr; R^1 is a halide; R^2 is a ligand selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silylated derivatives thereof, R^1 and R^2 may or may not be identical ligands; A is an optional coordinatively bound ligand selected from the group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, alkynes, hydrazine, pyridines, nitrogen heterocycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, alkylidenes, nitrites, or water; $x \geq 1$; $y \geq 0$; z is ≥ 0 ; and $x+y =$ the valence of element M.

(ii) inert liquid

wherein the inert liquid is selected from the group consisting of aliphatic hydrocarbons, aromatic hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkynitrile, halogenated hydrocarbons, silylated hydrocarbons, thioethers, amines, cyanates, isocyanates, thiocyanates, silicone oils, nitroalkyl, alkynitrate and/or mixtures of one or more of

the above. Preferably a liquid composed essentially of a C₅-C₁₂ alkane.

(iii) optional additive

5

In the case of unstable halide-containing compounds which have a tendency to decompose or chemically rearrange during storage or vaporization, additional halide ligands may be added to the mixture to improve the stability of 10 the compound. In the case of unstable adducts of halide-containing compounds, additional adducts may be added to the mixture to improve the stability of the compound. Other coordinating compounds may be added to the mixture to improve stability of the compound as well including: 15 phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfdes, nitriles, isonitriles, alkenes, pyridines, heterocycles, tetrahydrofuran, dimethylformamide, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, or alkynes. All 20 optional additives will comprise no more than 30% by volume of the inert liquid.

Preferred precursor source mixtures are comprised of TiCl₄; ZnCl₂; ZrCl₄; HfCl₄; AlCl₃; SiCl₄; GaCl₃; SnCl₄; 25 CoCl₃; dimethyl, diethyl, or diisobutyl, Al, B, Ge, Si, or As halide, dissolved, emulsified or suspended in a C₅-C₁₂ alkane liquid.

30 Precursor Source mixtures for silyl-containing compounds

Preferred precursor source mixtures of silyl-containing compounds are comprised of:

(i) $MR^1_xR^2_yA_z$

5

where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi, preferably Ti, Zr, Hf, Si, Ga, Sn, Co, V, or Cr; R^1 is a silyl; R^2 is a ligand selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silylated derivatives thereof, R^1 and R^2 may or may not be identical ligands; A is an optional coordinatively bound ligand selected from the group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, alkynes, hydrazine, pyridines, nitrogen heterocycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, alkylidenes, nitrites, and water; $x \geq 1$; $y \geq 0$; z is ≥ 0 ; and $x+y =$ the valence of element M.

(ii) inert liquid

wherein the inert liquid is selected from the group consisting of aliphatic hydrocarbons, aromatic hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkylnitrile, halogenated

hydrocarbons, silylated hydrocarbons, thioethers, amines,
cyanates, isocyanates, thiocyanates, silicone oils,
nitroalkyl, alkylnitrate and/or mixtures of one or more of
the above. Preferably a liquid composed essentially of a
5 C₅-C₁₂ alkane.

(iii) optional additive

In the case of unstable silyl-containing compounds which
10 have a tendency to decompose or chemically rearrange
during storage or vaporization, additional silyl ligands
may be added to the mixture to improve the stability of
the compound. In the case of unstable adducts of silyl
15 containing compounds, additional adducts may be added to
the mixture to improve the stability of the compound.
Other coordinating compounds may be added to the mixture
to improve stability of the compound as well including:
phosphines, phosphites, aryls, amines, arsines, stibenes,
ethers, sulfdes, nitriles, isonitriles, alkenes,
20 pyridines, heterocycles, tetrahydrofuran,
dimethylformamide, macrocycles, schiff bases,
cycloalkenes, alcohols, phosphine oxides, or alkynes. All
optional additives will comprise no more than 30% by
volume of the inert liquid.

25 Preferred precursor source mixtures are comprised of
N(SiMe₃)₂, Li, Na, or K; B(CH₂SiMe₃)₃; {(Me₃Si)₂N}₃, B, Al, Ga
or In; (Me₃SiCH₂)₄ Ti, Zr or Hf; {(Me₃Si)₂N}₂, Zn, Cd or Hg
dissolved, emulsified or suspended in a C₅-C₁₂ alkane
30 liquid.

The following examples are given to illustrate the present invention and to demonstrate some advantages that can arise therefrom.

00000000000000000000000000000000

EXAMPLE 1

Deposition of a Film in a Chemical Vapor Deposition
Reactor utilizing a Precursor Source Mixture

5 In this example, a substrate is placed in a suitable reactor for CVD, and a multicomponent metal, metal oxide, metal nitride or metal silicide Hf- and Al-containing film is deposited using two different precursor source mixtures.

10 The hafnium-containing precursor source mixture is comprised of 50 grams of tetrakis(dimethylamino) hafnium and 1 gram of dimethylamine in a liter of pentane. The aluminum-containing precursor source mixture is comprised of 50 grams of trimethylamine alone and 1 gram of trimethylamine in a liter of pentane. In this example, the precursor source mixtures are vaporized in an vaporizer and the vapor is introduced into the CVD reactor. The precursor source mixtures are vaporized at 40°-260°C, preferably 40°-180°C. The substrate temperature is from about 100°-1200°C, and preferably 200°-700°C. In order to deposit a metal film, a reducing reactant is introduced including, but not limited to: hydrogen, forming gas and combinations thereof. The preferred reductant is forming gas. In order to deposit a metal oxide film, an oxidant is introduced including, but not limited to: oxygen, ozone, water, hydrogen peroxide, nitrous oxide and combinations thereof. The preferred oxidant is oxygen. In order to deposit a metal nitride film, a nitriding reactant is introduced including, but not limited to: ammonia, hydrazine, hydrogen azide, tertbutylamine, and combinations thereof. The preferred

nitriding reactant is ammonia. In order to deposit a metal silicide film, a silyating agent including, but not limited to: silane, disilanes, chlorosilanes, silylamines, and silazanes, and a reducing agent are introduced into the CVD reactor along with the precursor vapor. The vapor of the precursor source mixtures and reactants are introduced simultaneously, preferably through separate inlets.

The inventive method described can be expanded to include growth of any multicomponent metal, metal oxide, metal nitride or metal silicide film deposited by chemical vapor deposition utilizing two or more different precursor source mixtures or utilizing a precursor source mixture which contains two or more precursors. The inventive method described can be expanded to include growth of any multicomponent metal, metal oxide, metal nitride or metal silicide film deposited by chemical vapor deposition providing at least one component of the multicomponent film is derived from a precursor source mixture. The other components of the film may be deposited utilizing conventional bubbler technology or precursor sources not covered in this invention. The inventive method described can be expanded to include growth of any single component metal, metal oxide, metal nitride or metal silicide film deposited by chemical vapor deposition utilizing one precursor source mixture which contains only one precursor.

30

EXAMPLE 2

Method of Film Growth wherein the inert liquid is not vaporized.

In this example, the inert liquid is not vaporized and is diverted from the CVD or ALD reactor. The precursor source mixtures is comprised of a precursor and an inert 5 liquid which vaporizes at a higher temperature than the precursor. The precursor source mixture is introduced into the vaporizer where the precursor is vaporized. The inert liquid is not vaporized, but instead is diverted from the reactor in liquid form.

10 One possible apparatus configuration is shown in Fig. 29. As shown in Fig. 29, the precursor source mixture would flow from the ampoule to the vaporizer. The precursor in the precursor source mixture would be vaporized in the 15 vaporizer, but the inert liquid would not. The vaporized precursor would be transported to the reactor, and the non-vaporized inert liquid would drain out of the vaporizer and be collected in a trap. The vaporizer temperature would be set at less than the boiling point of 20 the inert liquid.

25 One preferred method would comprise a precursor source mixtures composed of dimethylethylamine alane and decane (boiling point 174°C) with the vaporizer temperature set at 90°C.

The inventive method described can be expanded to include growth of any single or multicomponent film deposited by 30 chemical vapor deposition or atomic layer deposition, providing that the vaporizer temperature is sufficient to volatilize the precursor(s) and less than the boiling

point of the inert liquid in the precursor source mixture.

EXAMPLE 3

5 Deposition of a Metal, Metal Oxide, or Metal Nitride in a
Atomic Layer Deposition Reactor utilizing a Precursor
Source Mixture

In this embodiment, a substrate is placed in a suitable reactor for ALD, for example the commercial F-200 reactor
10 made by Microchemistry, and a multicomponent metal, metal oxide, or metal nitride film containing Zr and Hf is deposited using two different precursor source mixtures. ALD is performed in a cyclic fashion with sequential
15 alternating pulses of vaporized precursor, reactant and purge gas.

The zirconium-containing precursor source mixture is comprised of 50 grams of zirconium nitrate in a liter of pentane. The hafnium-containing precursor source mixture is comprised of 50 grams of hafnium tertbutoxide in a liter of pentane. In this example, the precursor source mixtures are vaporized in an vaporizer and the vapor is introduced into the reactor in a cyclical fashion. In order to deposit a metal film, a reducing reactant is introduced including, but not limited to: hydrogen, forming gas and combinations thereof. The preferred reductant is forming gas. In order to deposit a metal oxide film, an oxidant is introduced including, but not limited to: oxygen, ozone, water, hydrgoien peroxide,
25 nitrous oxide and combinations thereof. The preferred oxidant is water. In order to deposit a metal nitride film, a nitriding reactant is introduced including, but
30

not limited to: ammonia, hydrazine, hydrogen azide, tertbutylamine, and combinations thereof. The preferred nitriding reactant is ammonia.

5 The precursor source mixtures are vaporized at 40°-260°C, preferably 40°-180°C. The substrate temperature is about 100°- 1200°C, and preferably 150°-500°C. The precursor, reactant and inert purge gas (N₂ or Ar or other inert gas) are pulsed into the reactor in the following sequence:

- 10 1. vapor of Hf-containing precursor source mixture
 2. inert purge
 3. reactant
 4. inert purge
 5. vapor of Zr-containing precursor source mixture
15 6. inert purge
 7. reactant
 8. inert purge

20 The precursor and reactant pulses (steps 1, and 5, and 3, and 7, respectively) last 0.1 -1 second, preferably 0.5 seconds. The inert gas purge pulse (steps 2,4,6, and 8) last 0.2-5 seconds, preferably 2 seconds. Completion of steps 1 - 8 is a cycle, the completion of 1 cycle results in deposition of about 0.4-2 monolayer of ZrHf-containing film or roughly 0.1 nm. In this example, the preferred thickness of deposited ZrHf-containing film is 50 nm, so 25 500 cycles of gas switching as described above are performed.

30 The inventive method described can be expanded to include growth of any multicomponent metal, metal oxide, metal nitride or metal silicide film deposited by atomic layer deposition utilizing two or more different precursor

source mixtures or utilizing a precursor source mixture which contains two or more precursors. The inventive method described can be expanded to include growth of any multicomponent metal, metal oxide, metal nitride or metal silicide film deposited by atomic layer deposition providing at least one component of the multicomponent film is derived from a precursor source mixture. The other components of the film may be deposited utilizing conventional bubbler technology or precursor sources not covered in this invention. The inventive method described can be expanded to include growth of any single component metal, metal oxide, metal nitride or metal silicide film deposited by atomic layer deposition utilizing one precursor source mixture which contains only one precursor. In an alternative embodiment, the inert liquid is not vaporized and is diverted from the ALD reactor as described in Example 2.

EXAMPLE 4

20 Deposition of a Metal Silicide Film
in a Atomic Layer Deposition Reactor utilizing a
Precursor Source Mixture

In this example, a substrate is placed in a suitable reactor for ALD, for example the commercial F-200 reactor made by Microchemistry, and a cobalt silicide film is deposited. ALD is performed in a cyclic fashion with sequential alternating pulses of vaporized precursor, reactant and purge gas. In this example, silane is used as the silyating agent and hydrogen as the reactant.

The cobalt-containing precursor source mixture is comprised of 50 grams of $\text{Co}_2(\text{CO})_8$ and a liter of pentane. In this example, the precursor source mixtures are vaporized in a vaporizer and the vapor is introduced into

5 the reactor in a cyclical fashion.

The precursor source mixtures are vaporized at 40° - 260°C , preferably 40° - 180°C . The substrate temperature is about 100° - 1200°C , and preferably 200° - 800°C . The precursor,

10 reactant and inert purge gas (N_2 or Ar or other inert gas) are pulsed into the reactor in the following sequence :

1. vapor of Co-containing precursor source mixture
2. inert purge
3. hydrogen
4. inert purge
5. silane
6. inert purge
7. hydrogen
8. inert purge

20 The precursor and reactant pulses (steps 1, and 5, and 3, and 7, respectively) last 0.1 - 1 second, preferably 0.5 seconds. The inert gas purge pulse (steps 2,4,6, and 8) last 0.2-5 seconds, preferably 2 seconds. Completion of steps 1 - 8 is a cycle, the completion of 1 cycle results

25 in deposition of about 0.4-2 monolayer of Co silicide or roughly 0.1 nm. In this example, the preferred thickness of deposited Co silicide film is 500 nm, so 5000 cycles of gas switching as described above are performed.

30 The inventive method described can be expanded to include growth of any metal silicides including, but not limited to: CoSi_2 , HfSi_2 , MoSi_2 , NbSi_2 , Pd_2Si , PtSi , TaSi_2 , TiSi_2 ,

VSi₂, WSi₂, ZrSi₂ and any multicomponent metal silicide, deposited by atomic layer deposition which utilizes at least one precursor source mixture, and hydrogen or other reducing agent in sequence with silane or other silyating agent including, but not limited to: silane, disilanes, chlorosilanes, silylamines, silazanes. In an alternative embodiment, the silyating agent can be introduced in a precursor source mixture.

10

EXAMPLE 5
Deposition of Copper

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In this example, the inventive method is used to deposit copper. A copper-containing precursor source mixture comprised of 100 grams of (cyclopentadienyl)Cu(PEt₃), 1 gram of PEt₃ and 1 liter of pentane. The precursor mixture is transported to a vaporizer where the mixture is vaporized at 60°C and the vapor transported into the chemical vapor deposition reactor where a reductant such as hydrogen is present and a copper film is deposited on a substrate heated to 100°-300°C, preferably 120°-250°C.

EXAMPLE 6
Deposition of Tungsten

30

In this example, the inventive method is used to deposit tungsten. The precursor source mixture is composed of 100 grams of tungsten hexacarbonyl in a liter of hexane. The precursor mixture is transported to a vaporizer where the mixture is vaporized at 80°C and the vapor transported into the chemical vapor deposition reactor where a reductant such as hydrogen is present and a tungsten film

is deposited on a substrate heated to 200°-700°C,
preferably 600°C.

EXAMPLE 7

5

Deposition of Tantalum Nitride

In this example, the inventive method is used to deposit tantalum nitride. A tantalum containing precursor source mixture comprised of 100 grams of

10 pentadimethylaminotantalum, 1 gram of dimethylamine and 1 liter of pentane. The precursor mixture is transported to a vaporizer where the mixture is vaporized at 60°C and the vapor transported into the chemical vapor deposition reactor where a nitriding agent such as ammonia is present
15 and a tantalum nitride film is deposited on a substrate heated to 200°-700°C, preferably 500°C.

EXAMPLE 8

Deposition of Indium Nitride

20

In this example, the inventive method is used to deposit indium nitride. An indium-containing precursor source mixture comprised of 100 grams of trimethylindium dimethylethylamine, 1 gram of dimethylethylamine and 1 liter of pentane. The precursor mixture is transported to a vaporizer where the mixture is vaporized at 60°C and the vapor transported into the chemical vapor deposition reactor where a nitriding agent such as ammonia is present
25 and an indium nitride film is deposited on a substrate heated to 100°-700°C, preferably 300°C.
30

EXAMPLE 9
Deposition of Zirconium Silicate

In this example, the inventive method is used to deposit
5 zirconium silicate. The precursor source mixture is composed of 100 grams of zirconium tertbutoxide in liter of hexane. A second precursor source mixture is composed of 100 grams of tetraethoxysilane in liter of hexane. The precursor source mixtures are transported to a vaporizer
10 where the mixtures are vaporized at 80°C and the vapor transported into the chemical vapor deposition reactor where an oxidant such as oxygen is present and a zirconium silicate film is deposited on a substrate heated to 200°-700°C, preferably 500°C

15

EXAMPLE 10

Fabrication of a Al_2O_3 gate dielectric for a transistor

In this example, the inventive method is used to deposit
20 Al_2O_3 to form the gate dielectric layer 15 of the PFET and NFET as shown in Fig. 1. A Si wafer substrate containing patterned structures is used. Selected regions of the substrate contain shallow trench isolation (STI) oxide located between the sites of transistor, other regions contain the field oxide, and selected regions of bare Si are exposed in the regions where transistor are to be located. The substrate is then placed in a suitable modular cluster tool, the surface of the bare Si is treated to form a $\text{SiO}_{x,y}$ layer in-situ without breaking
25 vacuum, before a layer of Al_2O_3 is deposited to a thickness of 1-100 nm using the CVD process of this invention. The wafer is then transported to a second

module of the modular cluster tool where the gate electrode can be deposited on the Al₂O₃ in-situ without breaking vacuum.

5 For the deposition of the Al₂O₃ using the inventive method, the precursor source mixture is composed of 103 grams of dimethylethylamine alane and 10 grams of dimethylethylamine in a liter of hexane. The precursor mixture is transported to a vaporizer where the mixture is
10 vaporized at 80°C and the vapor transported into the chemical vapor deposition module of the cluster tool where an oxidant including, but not limited to: oxygen, ozone, N₂O, water, or mixtures thereof is present and an Al₂O₃ film is deposited at 200°C.

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EXAMPLE 11

Fabrication of a ZrO₂ gate dielectric for a transistor

In this example, the inventive method is used to deposit ZrO₂ to form the gate dielectric layer 15 of the PFET and NFET as shown in Fig. 1. A Si wafer substrate containing patterned structures is used. Selected regions of the substrate contain shallow trench isolation (STI) oxide located between the sites of transistor, other regions contain the field oxide, and selected regions of bare Si are exposed in the regions where transistor are to be located. The substrate is then placed in a suitable modular cluster tool, the surface of the bare Si is treated to form a SiO_xN_y layer in-situ without breaking vacuum, before a layer of ZrO₂ is deposited to a thickness of 1-100 nm using the CVD process of this invention. The wafer is then transported to a second module of the
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25
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modular cluster tool where the gate electrode can be deposited on the ZrO₂ in-situ without breaking vacuum.

For the deposition of the ZrO₂ using the inventive method,
5 the precursor source mixture is composed of 100 grams of zirconium tertbutoxide in a liter of hexane. The precursor mixture is transported to a vaporizer where the mixture is vaporized at 80°C and the vapor transported into the chemical vapor deposition module of the cluster
10 tool where an oxidant including, but not limited to: oxygen, ozone, N₂O, water, or mixtures thereof is present and an ZrO₂ film is deposited at 400°C.

EXAMPLE 12

15 Fabrication of a gate dielectric for a transistor

In this example, the inventive method is used to deposit the gate dielectric layer of a transistor. As shown in Fig. 4, a transistor device is formed on a conductivity region 51 and contains a gate electrode 52 formed on a gate dielectric 53 and a pair of n-type source/drain regions 54 formed on laterally opposite sides of gate electrode 52. Gate dielectric 53, which is deposited by the inventive method, may consist of doped or undoped mixtures, layers of different materials or combinations thereof. An optional upper layer 57 of gate dielectric 53 may act as a dopant diffusion barrier and stabilizes the structure during deposition of gate electrode 52. An optional lower layer 55 of gate dielectric 53 may act as an electron barrier layer and as a layer to prevent oxidation of the underlying silicon during processing or
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25
30

both. Middle layer 56 of gate dielectric 53 is a high K dielectric layer.

A suitable lower layer 55 is composed of dielectric materials including, but not limited to: SiO_2 , SiO_xN_y , Si_3N_4 , prepared from oxidation or nitridation of the silicon substrate or deposited separately. Other suitable lower layer materials include metal oxides or metal silicates. A middle high K dielectric layer 56 is composed of dielectric materials including, but not limited to: Ta_2O_5 , TiO_2 , ZrO_2 , HfO_2 , Al_2O_3 , La_2O_3 , Y_2O_3 , yttrium aluminate, lanthnaum aluminate, lanthanum silicate, yttrium silicate, hafnium silicate, zirconium silicate, doped or undoped mixtures, layers or combinations thereof. The middle layer may also be comprised of several layers of different materials such as a layer of hafnium oxide sandwiched between layers of aluminum oxide or a layer comprising a relatively homogenous mixture such as a mixture of zirconium oxide and hafnium oxide. Optional upper layer 57 may be an oxidized or nitrided surface of the middle layer, or a deposited dielectric material including, but not limited to: SiO_2 , SiO_xN_y , Si_3N_4 , ZrO_2 , HfO_2 , Al_2O_3 , aluminosilicate, yrtrrium silicate, zirconium silicate, hafnium silicate, lanthanum silicate doped or undoped mixtures, layers or combinations thereof. Preferred gate dielectrics are comprised of a lower layer of SiO_xN_y , a middle layer of Al_2O_3 , ZrO_2 , or HfO_2 and an upper barrier layer of the nitrided metal oxide. At least one of the components in gate dielectric 53 is deposited by the inventive method comprising a precursor source mixture, vaporization of the precursor source mixture and

deposition of a film with the vapor in a CVD or ALD reactor.

Figs. 5 through 12 are cross sectional views showing one preferred fabrication of a transistor using the inventive method. Fabrication of gate dielectric 53 is done in-situ in a cluster tool as manufactured by Applied Materials. In Fig. 5, a silicon substrate 50 with a clean (no native SiO_2) surface is the starting point. In Fig. 6, lower layer 55 has been formed by oxidation/nitridation of silicon substrate 50 to form a SiO_xN_y layer. In Fig. 6, a middle layer 56 of zirconium oxide has been formed by the inventive method, comprised of utilizing a precursor source mixture of zirconium t-butoxide and hexane, vaporizing the precursor source mixture at 80°C, and deposition of a ZrO_2 film in the presence of an oxidant such as oxygen, ozone, N_2O , H_2O or mixtures thereof at 400°C on the SiO_xN_y layer in a chemical vapor deposition reactor. In Fig. 7, upper layer 57 is formed by plasma nitridation of the ZrO_2 surface. In Fig. 8, polysilicon is deposited as gate electrode 52. In Figs. 9 through 12, the gates are formed, extension implant done, spacers 58 formed, and source/drain implants performed to produce a fully formed devices. The subsequent steps of contact formation, etc. are not shown.

EXAMPLE 13

Fabrication of a transistor using metal gates

In this example, the inventive method is used to fabricate a transistor using metal gates. As shown in Fig. 1, a CMOS integrated circuit contains both n-type field effect

transistors (NFET) and p-type field effect transistors (PFET) is formed on a single substrate 10. NFET device 11 is formed on a p-type conductivity region 13 of substrate 10 and contains a gate electrode 14 formed on a gate dielectric 15 and a pair of n-type source/drain regions 16 formed on laterally opposite sides of gate electrode 14. Similarly, PFET device 17 is formed on a n-type conductivity region 18 of substrate 10 and contains the gate electrode 19 formed on gate dielectric 15 and a pair of p-type conductivity source/drain regions 20 formed along opposite sidewalls of gate electrode 19. The NFET and PFET devices are separated by shallow trench isolation 21 and by spacers 22. In this example, the gate electrode 14 or 19 is comprised of a bulk metal or alloy having the appropriate work function. Metals suitable for the gate electrode 14 of the NFET device 11 include, but are not limited to: Al, Ag, Bi, Cd, Fe, Ga, Hf, In, Mn, Nb, Y, and Zr or alloys thereof. At least one metal suitable for the NFET may also be alloyed with W, Mo, Cr, and Cu to form gate electrode 14. Metals suitable for gate electrode 19 of PFET device 17 include, but are not limited to: Ni, Pt, Be, Ir, Te, Re and Rh. At least one metal suitable for the PFET may also be alloyed with W, Mo, Cr, and Cu to form gate electrode 19. In this embodiment, at least one of the NFET or PFET components is deposited by the inventive method including gate electrode 14, gate electrode 19 and/or gate dielectric 15. The gate dielectric 15 may be deposited by the inventive method as described in example 2.

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EXAMPLE 14
Fabrication of a transistor

In this example, the inventive method is used to fabricate
5 a transistor using metal gates. Figure 13 shows a generic
device structure including NFETs and PFETs. In this
embodiment NFET and PFET are formed on a single p-type
conducting substrate 60. NFET device 61 is formed on a
10 p-type conductivity region of substrate 60 and contains a
gate electrode 62 formed on a gate dielectric 64 and a
pair of n-type source/drain regions 65 formed on laterally
opposite sides of gate electrode 62. Similarly, PFET
device 71 is formed on a n-type well 72 of substrate 60
15 isolated by shallow trench isolation 73 and contains the
gate electrode 74 formed on gate dielectric 64 and a pair
of p-type conductivity source/drain regions 76 formed
along opposite sidewalls of gate electrode 74.

Figs. 14 through 23 are partial cross sectional views
20 showing one example of a possible fabrication sequence for
a standard CMOS flow. In Fig. 14, a silicon substrate 60
having shallow trench isolation (STI) 73 and an N-well 72
are formed in a portion of a p-type conducting substrate.
In Fig. 15, a gate dielectric 64 and a masking layer (for
25 example Si₃N₄) 77 have been formed on the substrate. Gate
dielectric 64 may be deposited according to the inventive
method as described in examples 12. In Fig. 16, an
opening in masking layer 77 where the NFET gate will go
has been formed. In Fig. 17, NFET gate electrode 62 has
30 been formed. Materials suitable for NFET gate electrode 62
include, but not limited to: polysilicon, W, Mo, Ti, Cr,
Cu, Fe, Mn, Nb, V, Re, Pt, Ag, Bi, Cd, Fe, Ga, Hf, In, Mn,

Y, Zr doped or undoped alloys, mixtures and multilayers, thereof. NFET gate electrode 62 may be deposited by the inventive method. In Fig. 18, a chemical-mechanical-polish (CMP) step has been done to planarize the surface. In Figs. 19 through 21 steps are shown which repeat those in Figs. 16-18 for the PFET device fabrication. In Fig. 19, an opening in masking layer 77 where the PFET gate will go has been formed. In Fig. 20, PFET gate electrode 74 has been formed. Materials suitable for gate electrode 74 for PFET include, but not limited to: polysilicon, Ni, W, Mo, Ti, Cr, Te, Cu, Pd, Pt, Be, Au, Ir, Te, Rh, doped or undoped alloys, mixtures and multilayers, thereof. PFET gate electrode 74 may be deposited by the inventive method. In Fig. 21, a chemical-mechanical-polish (CMP) step has been done to planarize the surface. In Fig. 22, extension implants are performed, one for the NFET, and one for the PFET, each through a blocking layer. In Fig. 23, source/drain implants are performed, after a spacer 78 formation process, one for the NFET, and one for the PFET, each through a blocking layer to complete device fabrication. In this embodiment, at least one or more of the layers or component of a layer, including the gate dielectric, gate electrode, is deposited by the inventive method comprising a precursor source mixture, vaporization of the precursor source mixture and deposition of a film using the vapor of the precursor source mixture in a CVD or ALD reactor.

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EXAMPLE 15
Fabrication of a stack capacitor.

In this example, an integrated circuit capacitor is
5 fabricated incorporating at least one component deposited
by the inventive method. As shown in Fig. 2, a typical
capacitor is formed on a substrate 30, connected by a plug
10 31 to a transistor, with a barrier 32 and consists of a
bottom electrode 33, a dielectric material 34 which may or
may not be ferroelectric, and a top electrode 35. In this
embodiment at least one of the capacitor components is
15 deposited by the inventive method including plug 31,
barrier 32, bottom electrode 33, a dielectric material 34
and/or top electrode 35.

15 Figs. 24 through 28 are partial cross sectional views
showing one example of a possible fabrication sequence for
a capacitor. In Fig. 24, a substrate 30 having a trench is
formed. Substrates include, but are not limited to:
20 Si-containing semiconductor substrates, silicon on
insulator substrates, Ge substrates, SiGe substrates, GaAs
substrates, and other like substrates, dielectrics,
metals, organic substrates, glasses, metal oxides, plastic
polymeric substrates and mixtures, combinations and layers
25 thereof. In Fig. 25, a plug material 31 and an optional
barrier 32 is formed. The plug material is composed of
conventional conductive materials including, but not
limited to: polysilicon, W, Mo, Ti, Cr, Cu, and may
30 be deposited utilizing the inventive method. Optional
conducting barrier 32 is composed of conventional
conducting materials including, but not limited to: TaN,
TaSiN, TiAlN, TiSiN, TaSiN, TaWN, TiWN, TaSiN, TaAlN, NbN,

ZrN, TaTiN, TiSiN, TiAlN, IrO₂, SiC, TiPt, TiNPt, TiAlN-Pt, Ru, RuO₂, RuPt, RuO₂, WSi, Ti, TiSi, doped and undoped polysilicon, Al, Pd, Ir, IrO_x, Os, OsO_x, MoSi, TiSi, ReO₂, mixtures or multilayers thereof and may be deposited utilizing the inventive method. In Fig. 26, a bottom electrode 33 is formed. The bottom electrode is composed of conductive materials including, but not limited to: polysilicon, Ni, Pd, Pt, Cu, Ag, Au, Ru, Ir, Rh, IrO_x, RuO_x, TaN, TaSiN, Ta, SrRuO₃, LaSrCoO₃, doped or undoped alloys, mixtures, or multilayers, thereof. In Fig. 27, a dielectric material 34 is formed. The dielectric material is composed of any insulating material including, but not limited to: SiO₂, SiO_xN_y, Si₃N₄, metal oxides such as Ta₂O₅, TiO₂, ZrO₂, HfO₂, Al₂O₃, La₂O₃, Y₂O₃ alloys, mixtures or layers thereof, or multicomponent metal oxides such as perovskite type oxides having the formula ABO₃ wherein B is at least one acid oxide containing a metal selected from the group consisting of Al, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W and Cu, and A is at least one additional cation having a positive formal charge of from about 1 to about 3. Examples include, but are not limited to: barium strontium titanate, zirconate, hafnate, lead titanate, yttrium aluminate, lanthanum aluminate, lead zirconium titanate, silicates such as hafnium silicate, zirconium silicate including rare earth doped silicates. In Fig. 28, a top electrode 35 is formed. The top electrode is composed of conductive materials including, but not limited to: polysilicon, Ni, Pd, Pt, Cu, Ag, Au, Ru, Ir, Rh, IrO_x, RuO_x, TaN, TaSiN, Ta, SrRuO₃, LaSrCoO₃, doped or undoped alloys, mixtures, or multilayer, thereof. The top and bottom electrode may or may not be similar. In this embodiment, at least one or

more of the layers, including the plug, barrier, bottom electrode, dielectric, and/or top electrode is deposited by the inventive method comprising a precursor source mixture, vaporization of the precursor source mixture and deposition of a film using the vapor of the precursor source mixture in a CVD or ALD reactor.

EXAMPLE 16

Fabrication of a trench capacitor

In this example, an integrated circuit trench capacitor is fabricated incorporating at least one component deposited by the inventive method. One possible example for fabricating a trench capacitor on a substrate 30 is shown in Figure 30. A capacitor recess is formed in the substrate 30 which is connected to underlying circuitry via plug 31. The circuitry is covered with a dielectric insulating layer (isolation dielectric) 83. Substrates include, but are not limited to Si-containing semiconductor substrates, silicon on insulator substrates, Ge substrates, SiGe substrates, GaAs substrates, and other like substrates, dielectrics, metals, organic substrates, glasses, metal oxides, plastic polymeric substrates and mixtures, combinations and layers thereof. Dielectric insulating layer (isolation dielectric) 83 is selected from any insulating material including, but not limited to: SiO_2 , SiO_xN_y , Si_3N_4 , phosphosilicate glass, or metal oxides such as Al_2O_3 doped or undoped mixtures, or multilayer, thereof. Over the plug and the capacitor recess is deposited in sequence, an optional conductive barrier layer 32, bottom electrode layer 33, dielectric layer 34, and a top electrode layer 35, and optional

dielectric buffer layer 36. The plug material is composed of conventional conductive materials including, but not limited to: polysilicon, W, Mo, Ti, Cr, Cu, and may be deposited utilizing the inventive method. Optional conductive barrier 32 is composed of conventional conductive materials including, but not limited to: TaN, TaSiN, TiAlN, TiSiN, TaSiN, TaWN, TiWN, TaSiN, TaAlN, NbN, ZrN, TaTiN, TiSiN, TiAlN, IrO₂, SiC, TiPt, TiNPt, TiAlN-Pt, Ru, RuO₂, RuPt, RuO₂, WSi, Ti, TiSi, doped and undoped polysilicon, Al, Pd, Ir, IrO_x, Os, OsO_x, MoSi, TiSi, ReO₂, mixtures or multilayers thereof and may be deposited utilizing the inventive method. Bottom electrode 33 is composed of conductive materials including, but not limited to: polysilicon, Ni, Pd, Pt, Cu, Ag, Au, Ru, Ir, Rh, IrO_x, RuO_x, TaN, TaSiN, Ta, SrRuO₃, LaSrCoO₃, doped or undoped alloys, mixtures, or multilayers thereof. Dielectric material 34 is composed of any insulating material including, but not limited to: SiO₂, SiO_xN_y, Si₃N₄, metal oxides such as Ta₂O₅, TiO₂, ZrO₂, HfO₂, Al₂O₃, La₂O₃, Y₂O₃ alloys, mixtures or layers thereof, or multicomponent metal oxides such as perovskite type oxides having the formula ABO₃ wherein B is at least one acid oxide containing a metal selected from the group consisting of Al, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W and Cu, and A is at least one additional cation having a positive formal charge of from about 1 to about 3. Examples include, but are not limited to: barium strontium titanate, zirconate, hafnate, lead titanate, yttrium aluminate, lanthanum aluminate, lead zirconium titanate, silicates such as hafnium silicate, zirconium silicate including rare earth doped silicates. Top electrode 35 is composed of conductive materials including, but not

limited to: polysilicon, Ni, Pd, Pt, Cu, Ag, Au, Ru, Ir,
Rh, IrO_x , RuO_x , TaN, TaSiN, Ta, SrRuO_3 , LaSrCoO_3 , doped or
undoped alloys, mixtures, or multilayer, thereof. The top
and bottom electrode may or may not be similar. The
5 optional dielectric barrier is composed of any insulating
material including, but not limited to: SiO_2 , SiO_xN_y , Si_3N_4 ,
 TiON , AlN, SiN, TiN, metal oxides such as Ta_2O_5 , TiO_2 ,
 ZrO_2 , HfO_2 , Al_2O_3 , La_2O_3 , Y_2O_3 , alloys, mixtures or layers
thereof, or multicomponent metal oxides. The sequentially
10 deposited layers are planarized to yield a trench
capacitor in the capacitor recess. An insulating
passivation layer 37 and an inter-layer dielectric layer
38 are deposited to form a barrier structure over the
trench capacitor in the capacitor recess. Insulating
15 passivation layer 37 is composed of any insulating
material including, but not limited to: SiO_2 , SiO_xN_y , Si_3N_4 ,
 TiON , AlN, SiN, TiN, metal oxides such as Ta_2O_5 , TiO_2 ,
 ZrO_2 , HfO_2 , Al_2O_3 , La_2O_3 , Y_2O_3 , alloys, mixtures or layers
thereof, or multicomponent metal oxides. Inter-layer
20 dielectric 38 is selected from any insulating material
including, but not limited to: SiO_2 , SiO_xN_y , Si_3N_4 ,
phosphosilicate glass, or metal oxides such as Al_2O_3 doped
or undoped mixtures, or multilayers, thereof. A via is
formed in the barrier structure. A diffusion barrier
25 layer 81 and a metallazation layer 82 is deposited over
the barrier structure and via. Diffusion barrier layer 81
includes, but not limited to: WN, TiN, or TaN.
Metallazation layer 82 is selected from any conductive
material including, but not limited to: Al, W, Mo, Ti, Cr,
30 or Cu doped or undoped alloys, mixtures, or layers
thereof. In this embodiment, at least one of the trench
capacitor components including, but not limited to:

conductive barrier material, bottom electrode, dielectric material, top electrode, insulating passivation layer, inter-layer dielectric, diffusion barrier layer, isolation dielectric, and metallization layer is deposited by the
5 inventive method.

EXAMPLE 17
Fabrication of a Wiring Structure

10 In this example, an integrated circuit wiring structure is fabricated incorporating at least one component deposited by the inventive method. As shown in Fig. 3a, a typical wiring structure is formed by etching trenches 41 and vias 42 into a dielectric layer 43 selected from any insulating
15 material including, but not limited to: SiO_2 , SiO_xN_y , Si_3N_4 , phosphosilicate glass, or metal oxides such as Al_2O_3 doped or undoped mixtures, or multilayers, thereof. The metallization layer may be patterned by a damascene or a dual damascene process or by lithography and etching.
20 Below dielectric layer 43 is a metal thin film wire 44, selected from any conductive material including, but not limited to: Al, W, Mo, Ti, Cr, or Cu alloys, mixtures, or layers thereof, and a dielectric layer 45 selected from any insulating material including, but not limited to:
25 SiO_2 , SiO_xN_y , Si_3N_4 , phosphosilicate glass, or metal oxides such as Al_2O_3 doped or undoped mixtures, or multilayer, thereof. In Fig. 3b, the trench and via are filled with a barrier material 46, including, but not limited to: WN, TiN, or TaN and a wiring metal 47 selected from any
30 conductive material including, but not limited to: Al, W, Mo, Ti, Cr, or Cu doped or undoped alloys, mixtures, or layers thereof. In this embodiment, at least one of the

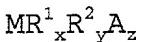
wiring structure components is deposited by the inventive method including dielectric layer, metal thin film wire, barrier material, and/or wiring metal.

5 While the present invention has been particularly shown and described with respect to preferred embodiments thereof, it will be understood by those skilled in the art that the foregoing and other changes in form and detail may be made without departing from the spirit and scope of the present
10 invention. It is therefore intended that the present invention not be limited to the exact forms and details described and illustrated, but fall within the scope of the appended claims.

CLAIMS

Having thus described our invention in detail, what we claim is new, and desire to secure by the Letters Patent is:

- 1 1. A precursor source mixture comprising at least one
2 precursor compound which is dissolved, emulsified or
3 suspended in an inert liquid, said at least one precursor
4 compound having the formula:



where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi; R¹ and R² are the same or different ligands selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and halogenated, sulfonated or silylated derivatives thereof; A is an optional coordinatively bound or associated ligand selected from the group consisting of phosphines, phosphites, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, hydrazine, pyridines, nitrogen heterocycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, alkylidenes, nitrites, alkynes, and water; x ≥ 1; x+y = the valence of element M; and z is ≥ 0.

- 1 2. The precursor source mixture of Claim 1 wherein said
2 inert liquid is an aliphatic hydrocarbon, aromatic
3 hydrocarbon, alcohol, ether, aldehyde, ketone, acid,
4 phenol, ester, amine, alkynitrile, halogenated

5 hydrocarbon, silylated hydrocarbon, thioether, amine,
6 cyanate, isocyanate, thiocyanate, silicone oil,
7 nitroalkyl, alkynitrate, or mixtures thereof.

1 3. The precursor source mixture of Claim 1 wherein M is
2 Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V,
3 Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd,
4 Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn,
5 Pb, As, P, Sb or Bi; R¹ is a hydride; R² is a hydride,
6 alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl,
7 amido, imido, hydrazido, phosphido, nitrosyl, nitryl,
8 nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, or
9 halogenated, sulfonated or silylated derivatives thereof;
10 and A is a phosphine, phosphite, aryl, amine, arsine,
11 stibene, ether, sulfide, nitrile, isonitrile, alkene,
12 alkyne, hydrazine, pyridine, nitrogen heterocycle,
13 macrocycle, schiff base, cycloalkene, alcohol, phosphine
14 oxide, alkylidene, nitrite or water.

1 4. The precursor source mixture of Claim 1 wherein M is
2 Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo,
3 W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn,
4 Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi;
5 R¹ is a C₁-C₈ alkyl, or C₄-C₁₂ cycloalkyl; R² is a hydride,
6 alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl,
7 amido, imido, hydrazido, phosphido, nitrosyl, nitryl,
8 nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, or
9 halogenated, sulfonated or silylated derivatives thereof;
10 and A is a phosphine, phosphite, aryl, amine, arsine,
11 stibene, ether, sulfide, nitrile, isonitrile, alkene,
12 alkyne, hydrazine, pyridine, nitrogen heterocycle,

13 macrocycle, schiff base, cycloalkene, alcohol, phosphine
14 oxide, alkylidene, nitrite, or water.

1 5. The precursor source mixture of Claim 1 wherein M is
2 Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo,
3 W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn,
4 Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi;
5 R¹ is a C₂-C₈ alkenyl, C₄-C₁₂ cycloalkenyl or C₅-C₁₈ aryl; R²
6 is a hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne,
7 carbonyl, amido, imido, hydrazido, phosphido, nitrosyl,
8 nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy,
9 silyl, and/or halogenated, sulfonated or silylated
10 derivatives thereof; and A is a phosphine, phosphite,
11 aryl, amine, arsine, stibene, ether, sulfide, nitrile,
12 isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen
13 heterocycle, macrocycle, schiff base, cycloalkene,
14 alcohol, phosphine oxide, alkylidene, nitrite, or water.

1 6. The precursor source mixture of Claim 1 wherein M is
2 Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo,
3 W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn,
4 Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi;
5 R¹ is a carbonyl; R² is a hydride, alkyl, alkenyl,
6 cycloalkenyl, aryl, alkyne, carbonyl, amido, imido,
7 hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile,
8 halide, azide, alkoxy, siloxy, silyl, and/or halogenated,
9 sulfonated or silylated derivatives thereof; and A is a
10 phosphine, phosphite, aryl, amine, arsine, stibene, ether,
11 sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine,
12 pyridine, nitrogen heterocycle, macrocycle, schiff base,
13 cycloalkene, alcohol, phosphine oxide, alkylidene,
14 nitrite, or water.

1 7. The precursor source mixture of Claim 1 wherein M is
2 Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo,
3 W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn,
4 Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi;
5 R¹ is an alkoxy or siloxy; R² is a hydride, alkyl,
6 alkenyl, cycloalkenyl, aryl, alkyne, carbonyl; amido,
7 imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate,
8 nitrile, halide, azide, alkoxy, siloxy, silyl, and/or
9 halogenated, sulfonated or silylated derivatives thereof;
10 and A is a phosphine, phosphite, aryl, amine, arsine,
11 stibene, ether, sulfide, nitrile, isonitrile, alkene,
12 alkyne, hydrazine, pyridine, nitrogen heterocycle,
13 macrocycle, schiff base, cycloalkene, alcohol, phosphine
14 oxide, alkylidene, nitrite, or water.

1 8. The precursor source mixture of Claim 1 wherein M is
2 Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo,
3 W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn,
4 Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi;
5 R¹ is an amide; R² is a hydride, alkyl, alkenyl,
6 cycloalkenyl, aryl, alkyne, carbonyl, amido, imido,
7 hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile,
8 halide, azide, alkoxy, siloxy, silyl, and/or halogenated
9 and sulfonated or silylated derivatives thereof; and A is a
10 phosphine, phosphite, aryl, amine, arsine, stibene, ether,
11 sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine,
12 pyridine, nitrogen heterocycle, macrocycle, schiff base,
13 cycloalkene, alcohol, phosphine oxide, alkylidene,
14 nitrite, or water.

1 9. The precursor source mixture of Claim 1 wherein the
2 precursor compound has the formula $MR_x^1(PR_3^2)_yA_z$ where M is
3 Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co,
4 Rh, Ir, Ni, Pd, Pt, Cu, Ag or Au, R¹ and R² is a ligand
5 selected from the group consisting of hydride, alkyl,
6 alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido,
7 imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate,
8 nitrile, halide, azide, alkoxy, siloxy, silyl, and/or
9 halogenated, sulfonated or silylated derivatives thereof;
10 A is an optional coordinatively bound ligand selected from
11 the group consisting of phosphines, phosphites, aryls,
12 amines, arsines, stibenes, ethers, sulfides, nitriles,
13 isonitriles, alkenes, alkynes, hydrazine, pyridines,
14 nitrogen heterocycles, macrocycles, schiff bases,
15 cycloalkenes, alcohols, phosphine oxides, alkylidenes,
16 nitrites and water; x ≥ 1; y ≥ 0; z is ≥ 0; and x+y = the
17 valence of M.

1 10. The precursor source mixture of Claim 1 wherein M
2 is Li, Na, K, Rb, Cs, Fr, Be, Mg, Sc, Y, La, Ce, Pr, Nd,
3 Sm, Eu, Gd, Tb, Dy, Ho, Er, Tm, Yb, Lu, Th, Pa, U, Ti, Zr,
4 Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir,
5 Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si,
6 Ge, Sn, Pb, As, Sb or Bi; R¹ is a nitrate; R² is a
7 hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne,
8 carbonyl, amido, imido, hydrazido, phosphido, nitrosyl,
9 nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy,
10 silyl, or halogenated, sulfonated or silylated derivatives
11 thereof; and A is a phosphine, phosphite, aryl, amine,
12 arsine, stibene, ether, sulfide, nitrile, isonitrile,
13 alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle,

14 macrocycle, schiff base, cycloalkene, alcohol, phosphine
15 oxide, alkylidene, nitrite, or water.

1 11. The precursor source mixture of Claim 1 wherein M is
2 Li, Na, K, Rb, Cs, Fr, Be, Mg, Sc, Y, La, Ce, Pr, Nd, Sm,
3 Eu, Gd, Tb, Dy, Ho, Er, Tm, Yb, Lu, Th, Pa, U Ti, Zr, Hf,
4 V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni,
5 Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge,
6 Sn, Pb, As, Sb or Bi; R¹ is a halide; R² is a hydride,
7 alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl,
8 amido, imido, hydrazido, phosphido, nitrosyl, nitryl,
9 nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl,
10 or halogenated, sulfonated or silylated derivatives
11 thereof; and A is a phosphine, phosphite, aryl, amine,
12 arsine, stibene, ether, sulfide, nitrile, isonitrile,
13 alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle,
14 macrocycle, schiff base, cycloalkene, alcohol, phosphine
15 oxide, alkylidene, nitrite or water.

1 12. The precursor source mixture of Claim 1 wherein M Li,
2 Na, K, Rb, Cs, Fr, Be, Mg, Sc, Y, La, Ce, Pr, Nd, Sm, Eu,
3 Gd, Tb, Dy, Ho, Er, Tm, Yb, Lu, Th, Pa, U Ti, Zr, Hf, V,
4 Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd,
5 Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn,
6 Pb, As, Sb or Bi; R¹ is a silyl; R² is a hydride, alkyl,
7 alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido,
8 imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate,
9 nitrile, halide, azide, alkoxy, siloxy, silyl, and/or
10 halogenated, sulfonated or silylated derivatives thereof;
11 and A is a phosphine, phosphite, aryl, amine, arsine,
12 stibene, ether, sulfide, nitrile, isonitrile, alkene,
13 alkyne, hydrazine, pyridine, nitrogen heterocycle,

14 macrocycles, schiff base, cycloalkene, alcohol, phosphine
15 oxide, alkylidene, nitrite or water.

1 13. The precursor source mixture of Claim 1 wherein M is
2 Pt; R¹ and R² are hydride, alkyl, alkenyl, cycloalkenyl,
3 aryl, alkyne, carbonyl, amido, imido, hydrazido,
4 phosphido, nitrosyl, nitryl, nitrate, nitrile, halide,
5 azide, alkoxy, siloxy, silyl, or halogenated or sulfonated
6 derivatives thereof; and A is a phosphine, phosphite,
7 aryl, amine, arsine, stibene, ether, sulfide, nitrile,
8 isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen
9 heterocycle, macrocycle, schiff base, cycloalkene,
10 alcohols, phosphine oxides, alkylidene, nitrites or water,
11 with the proviso sthat the compound is not
12 (cyclopentadienyl)Pt(alkyl)₃.

1 14. The precursor source mixture of Claim 1 wherein said
2 inert liquid vaporizes at a higher temperature than said
3 at least one precursor compound.

1 15. The precursor source mixture of Claim 2 wherein said
2 inert liquid is a C₅₋₁₂ alkane.

1 16. The precursor source mixture of Claim 1 wherein said
2 inert liquid contains an additive of no more than 30% by
3 volume of the inert liquid.

1 17. The precursor source mixture of Claim 16 wherein said
2 additive is an additional precursor ligand, an additional
3 precursor adduct, or other coordinating compound selected
4 from the group consisting of phosphines, phosphites,
5 aryls, amines, arsines, stibenes, ethers, sulfides,

6 nitriles, isonitriles, alkenes, pyridines, heterocycles,
7 tetrahydrofuran, dimethylformamide, marcrocycles, schiff
8 bases, cycloalkenes, alcohols, phosphine oxides and
9 alkynes.

1 18. The precursor source mixture of Claim 16 wherein the
2 additive is selected from the group consisting of
3 methanol, ethanol, isopropanol, neopentanol,
4 trimethylamine, dimethylethylamine, diethylmethyamine,
5 triethylamine, dimethylamine, diethylamine,
6 bistrimethylsilylamine, ammonia, ethylenediamine,
7 propylenediamine, trimethylethylene diamine,
8 triphenylphosphine, triethylphosphine, trimethylphosphine,
9 allyl, cyclopentadiene, benzene, ethylbenzene, toluene,
10 cyclohexadiene, cyclooctadiene, cycloheptatriene,
11 cyclooctatetraene, mesitylene, tetrahydroguran,
12 dimethylformamide, dimethylsulfoxide, butyl acetate,
13 acetic acid, ethylhexanoic acid, methane, ethane,
14 pyridine, and PF₃.

1 19. The precursor source mixture of Claim 1 wherein the
2 inert liquid is composed of two or more components
3 selected from the group consisting of aliphatic
4 hydrocarbons, aromatic hydrocarbons, alcohols, ethers,
5 aldehydes, ketones, acids, phenols, esters, amines,
6 alkynitrile, halogenated hydrocarbons, silylated
7 hydrocarbons, thioethers, amines, cyanates, isocyanates,
8 thiocyanates, silicone oils, nitroalkyl, alkynitrate,
9 and/or mixtures of one or more of the above and an
10 additive of no more than 30% by volume of the inert liquid
11 wherein the additive is selected from the group consisting
12 of additional precursor ligand, additional precursor

1 adduct, and other coordinating compound selected from the
2 group consisting of phosphines, phosphites, aryls, amines,
3 arsines, stibenes, ethers, sulfides, nitriles,
4 isonitriles, alkenes, pyridines, heterocycles,
5 tetrahydrofuran, dimethylformamide, macrocycles, schiff
6 bases, cycloalkenes, alcohols, phosphine oxides, and
7 alkynes.

1 20. The precursor source mixture of Claim 19 wherein the
2 additive is selected from the group consisting of
3 methanol, ethanol, isopropanol, neopentanol,
4 trimethylamine, dimethylethylamine, diethylmethylamine,
5 triethylamine, dimethylamine, diethylamine,
6 bistrimethylsilylamine, ammonia, ethylenediamine,
7 propylenediamine, trimethylethylene diamine,
8 triphenylphosphine, triethylphosphine, trimethylphosphine,
9 allyl, cyclopentadiene, benzene, ethylbenzene, toluene,
10 cyclohexadiene, cyclooctadiene, cycloheptatriene,
11 cyclooctatetraene, mesitylene, tetrahydroguran,
12 dimethylformamide, dimethylsulfoxide, butyl acetate,
13 acetic acid, ethylhexanoic acid, methane, ethane,
14 pyridine, and PF₃.

1 21. The precursor source mixture of Claim 1 wherein the
2 inert liquid is composed of C₅-C₁₂ alkane and contains an
3 additive of no more than 30% by volume of the inert liquid
4 wherein the additive is selected from the group consisting
5 of an additional precursor ligand, an additional precursor
6 adduct, or other coordinating compound selected from the
7 group consisting of phosphines, phosphites, aryls, amines,
8 arsines, stibenes, ethers, sulfides, nitriles,
9 isonitriles, alkenes, pyridines, heterocycles,

10 tetrahydrofuran, dimethylformamide, marcrocycles, schiff
11 bases, cycloalkenes, alcohols, phosphine oxides, and
12 alkynes.

1 22. The precursor source mixture of Claim 21 wherein the
2 additive is methanol, ethanol, isopropanol, neopentanol,
3 trimethylamine, dimethylethylamine, diethylmethylamine,
4 triethylamine, dimethylamine, diethylamine,
5 bistrimethylsilylamine, ammonia, ethylenediamine,
6 propylenediamine, trimethylethylethylenediamine,
7 triphenylphosphine, triethylphosphine, trimethylphosphine,
8 allyl, cyclopentadiene, benzene, ethylbenzene, toluene,
9 cyclohexadiene, cyclooctadiene, cycloheptatriene,
10 cyclooctatetraene, mesitylene, tetrahydroguran,
11 dimethylformamide, dimethylsulfoxide, butyl acetate,
12 acetic acid, ethylhexanoic acid, methane, ethane,
13 pyridine, or PF₃.

1 23. The precursor source mixture of Claim 1 wherein the
2 at least one precursor compound is dimethyl-, diethyl-, or
3 diisobutyl-B, Al, Ga, In, As, or Sb hydride;
4 Me₂AlH(NEtMe₂); tertbutylarsine; (Me₃N)AlH₃; (EtMe₂N)AlH₃;
5 (Et₃N)AlH₃; CpWH₂; Cp₂MoH₂; trimethyl-, triethyl-,
6 triisobutyl-, tri-n-propyl-, tri-isopropyl-, tri-n-butyl-,
7 trineopentyl-, or ethyldimethyl- B, Al, Ga, In, As or Sb;
8 tetramethyl-, tetraethyl-, tetraphenyl-, or tetra-n-butyl-
9 Si, Ti, Zr, Hf, Ge, Sn, or Pb; dimethyl-, diethyl-, or
10 diisobutyl- B, Al, Ga, In, As or Sb, hydride, chloride,
11 fluoride, bromide, iodide, Cp, amide, dimethylamide or
12 azide; triethyl-, triisobutyl-, tri-n-propyl-, tri-
13 isopropyl-, tri-n-butyl- or ethyldimethyl- B, Al, Ga, In,
14 As or Sb trimethylamine, diethylmethylamine,

15 dimethylethylamine, or triethylamine; dimethyl- or
16 diethyl- Zn, Cd, or Hg; (neopentyl)₄Cr; Et₃Pb(neopentoxy);
17 Cp₂Me₂Zr; (MeNC)₂PtMe₂; CpIr(C₂H₄)₂; bisCp- Co, Mo, Fe, Mn,
18 Ni, Ru, V, Os, Mg or Cr; bisethylbenzene; bisbenzene-Co,
19 Mo or Cr; triphenyl-Bi, Sb, or As; trivinylboron; trisCp-
20 Sc, Y, La, Ce, Pr, Nd, Sm, Eu, Gd, Tb, D, Ho, Er, Tm, Yb,
21 or Lu; tetraCp-Th, Pa, U, Np, Pu, or Am trisallyliridium;
22 CpCr(CO)₂; Cp₂ZrMe₂; CpCuP₃; CpIn; CpIr(cyclooctadiene);
23 CpPd(allyl); CpGaMe₂; CpGaEt₂; (cyclohexadiene)FeCO₃;
24 (cyclooctatetraene)FeCO₃; ethylferrocene; CpMn(CO)₃;
25 (cycloheptatriene) Mo(CO)₃; TlCp; Cp₂WH₂;
26 (mesitylene)W(CO)₃; CpRe(CO)₃; CpRh(CO)₂; Ir(allyl)₃;
27 Pt(allyl)₂; CpIr(cyclooctanedione);
28 [Ir(OMe)(cyclooctanedione)]₂;
29 Ru(cyclooctanedione)(allyl)₂; Ru₃CO₁₂; Fe(CO)₅; Co₂(CO)₈;
30 Ru(CO)₃ (1,3-cyclohexadiene); Os₃CO₁₂; Cr(CO)₆; CpCo(CO)₂;
31 Mn₂(CO)₁₀; CpMn(CO)₃; (cycloheptatriene)Mo(CO)₃; Mo(CO)₆;
32 Ni(CO)₄; Re₂(CO)₁₀; CpRe(CO)₃; CpRh(CO)₂; Ru₃(CO)₁₂; W(CO)₆;
33 CpV(CO)₄; CF₃Co(CO)₄; Pt(CO)₂(cyclooctanedione);
34 Ir(CO)₂(cyclooctanedione); (CO)₄Fe[P(OCH₃)₃];
35 (CO)₄Fe[N(CH₃)₃]; CoNO(CO)₃; butoxy, OCH(CF₃)₂, OCMe₂(CF₃),
36 OCMe(CF₃)₂, OSi(CH₃)₃, OC(CH₃)₃, OC(SiMe₃)₃, or OC(CF₃)₃ Li,
37 Na, K, Rb, Cs, Fr, Cu, Ag, Au, Hg, or Tl; tetra-methoxy,
38 tetra-ethoxy, tetra-isopropoxy, tetra-butoxy, tetra-tert-
39 butoxy, tetra-isobutoxy, tetra-OCH(CF₃)₂, tetra-OCMe₂(CF₃),
40 tetra-OCMe(CF₃)₂, tetra-OC(CH₃)₃, tetra-OC(SiMe₃)₃, tetra-
41 OC(CF₃)₃, or tetra-OSi(CH₃)₃ Si, Ge, Sn, Pb, Ti, Zr, or Hf;
42 VO(isopropoxy)₃, tri-isopropoxy, tri-sec-butoxy, tri-
43 n-butoxy, tri-iso-butoxy, tri-methoxy, tri-ethoxy, tri-
44 OCH(CF₃)₂, tri-OCMe₂(CF₃), tri-OCMe(CF₃)₂, tri-OC(CH₃)₃, tri-
45 OC(SiMe₃)₃, tri-OC(CF₃)₃, or tri-OSi(CH₃)₃, B, Al, Ga, In,
46 P, As, or Sb; Et₃Pb(isopropoxide); (tertbutoxy)CuPMe₃;

47 tetrakis(dimethylamino), tetrakis(diethylamino) Ti, Zr,
48 Hf, Si, Ge, Sn, or Pb; diethylaminodiethylarsine;
49 diethylaminoarsine dichloride; bisdimethylaminoarsine
50 chloride; Me₂Zn(triethylamine)₂;
51 diethylaminodimethylstannane; tris(dimethylamino)
52 phosphine; tris(dimethylamino) antimony;
53 tris(dimethylamino) arsine; tris(dimethylamino) stibine;
54 tris-bis(trimethylsilyl)erbium amide;
55 bis(dimethylamino)(trimethylethylethylenediamino)
56 aluminium; (CO)₄Fe[N(CH₃)₃]₂, Li, Na, or K N(SiMe₃)₂,
57 pentadimethylaminotantalum; diethylaminodimethyltin;
58 hexadimethylaminoditungsten;
59 trisdimethylamino(trimethylethylenediamino)titanium;
60 CpCu(PEt₃); CpCu(triphenylphosphine); (tertbutoxy)CuPMe₃;
61 Pt(PF₃)₄; Ni(PF₃)₄; Cr(PF₃)₆; (Et₃P)₃Mo(CO)₃; Ir(PF₃)₄;
62 Ti(NO₃)₄; Zr(NO₃)₄; Hf(NO₃)₄; Si(CH₃)₃(NO₃)₂; RuNO(NO₃)₃;
63 gallium nitrate; Sn(NO₃)₄; Co(NO₃)₃; VO(NO₃)₃; CrO₂(NO₃)₂;
64 TiCl₄; ZnCl₂; ZrCl₄; HfCl₄; AlCl₃; SiCl₄; GaCl₃; SnCl₄;
65 CoCl₃; dimethyl, diethyl, or diisobutyl, Al, B, Ge, Si, or
66 As halide; N(SiMe₃)₂, Li, Na, or K; B(CH₂SiMe₃)₃; {(Me₃Si)₂N}₃,
67 B, Al, Ga or In; (Me₃SiCH₂)₄Ti, Zr or Hf; or {(Me₃Si)₂N}₂
68 Zn, Cd or Hg, where Cp is cyclopentadienyl.

1 24. A method for chemical vapor deposition or atomic layer
2 deposition comprising: vaporizing the precursor compound
3 in the precursor source mixture of Claim 1, introducing
4 the vaporized precursor into a chemical vapor deposition
5 or atomic layer deposition reactor with optional addition
6 of other co-reactant(s), and depositing a constituent of
7 the vaporized precursor on a substrate to form a film.

1 25. The method of Claim 24 wherein said film is a
2 component in an electronic device.

1 26. The method of Claim 24 wherein said co-reactant(s) is
2 introduced separately from said vaporized precursor.

1 27. The method of Claim 24 comprising vaporizing the
2 precursor in the precursor source mixture, and introducing
3 the vaporized precursor into an atomic layer deposition
4 reactor with separate addition of other co-reactant(s) and
5 inert purge gas and depositing a film on a substrate by
6 sequential introduction of alternating pulses of vaporized
7 precursor(s), purge gas, co-reactant(s) and purge gas.

1 28. The method of Claim 24 wherein the co-reactant is a
2 reducing agent, an oxidizing agent, a nitriding agent or a
3 silyating agent.

1 29. The method of Claim 28 wherein said reducing agent is
2 selected from the group consisting of hydrogen, forming
3 gas, silane, and combinations thereof.

1 30. The method of Claim 28 wherein said oxidizing agent is
2 selected from the group consisting of oxygen, ozone,
3 water, hydrogen peroxide, nitrous oxide, and combinations
4 thereof.

1 31. The method of Claim 28 wherein said nitriding agent is
2 selected from the group consisting of ammonia, hydrazine,
3 hydrogen azide, tertbutylamine, isopropylamine, and
4 combinations thereof.

1 32. The method of Claim 28 wherein said silyating agent is
2 selected from the group consisting of silane, disilanes,
3 chlorosilanes, silylamines, silazanes, and combinations
4 thereof.

1 33. The method of Claim 24 comprising subjecting said
2 substrate to a sequence of alternating pulses of three or
3 more different gases wherein one of said gases comprises
4 vaporized precursor of said precursor source mixture,
5 another of said gases is a purge gas and another of said
6 gases is a reducing agent.

1 34. The method of Claim 24 comprising subjecting said
2 substrate to a sequence of alternating pulses of three or
3 more different gases wherein one of said gases comprising
4 said vaporized precursor of said precursor source mixture,
5 another of said gases is a purge gas and another of said
6 gases is an nitriding agent.

1 35. The method of Claim 24 comprising subjecting said
2 substrate to a sequence of alternating pulses of four or
3 more different gases, wherein one of said gases comprises
4 said vaporized precursor of said precursor source mixture,
5 another of said gases is a purge gas, another of said
6 gases is an oxidizing agent and another of said gases is
7 selected from the group consisting of any vaporized
8 precursor and a vaporized precursor of a precursor source
9 mixture according to Claim 1.

1 36. The method of Claim 24 comprising subjecting said
2 substrate to a sequence of alternating pulses of four or
3 more different gases, wherein one of said gases comprises

4 vaporized precursor of said precursor source mixture,
5 another of said gases is a purge gas, another of said
6 gases is an nitriding agent and another of said gases is
7 selected from the group consisting of any vaporized
8 precursor and a vaporized precursor of a precursor source
9 mixture according to Claim 1.

1 37. The method of Claim 24 comprising subjecting said
2 substrate to a sequence of alternating pulses of four or
3 more different gases, wherein one of said gases comprises
4 vaporized precursor of said precursor source mixture,
5 another of said gases is a purge gas, another of said
6 gases is a reducing agent and another of said gases is
7 selected from the group consisting of any vaporized
8 precursor and a vaporized precursor of a precursor source
9 mixture according to Claim 1.

1 38. The method of Claim 24 comprising subjecting said
2 substrate to a sequence of alternating pulses of five or
3 more different gases, wherein one of said gases comprises
4 vaporized precursor of said precursor source mixture,
5 another of said gases is a purge gas, another of said
6 gases is a reducing agent and another of said gases is
7 selected from the group consisting of any Si containing
8 vaporized precursor and a Si containing vaporized
9 precursor of a precursor source mixture according to
10 Claim 1.

1 39. The method of Claim 24 wherein the substrate is
2 selected from the group consisting of semiconductor
3 substrates, dielectrics, metals, organic substrates,
4 glasses, metal oxides, and plastic polymeric substrates,

5 Si-containing semiconductor substrates, ceramics, silicon-
6 on- insulator substrates, Ge substrates, SiGe substrates,
7 GaAs substrates, and mixtures or multilayers thereof.

1 40. The method of Claim 25 wherein said electronic device
2 is a transistor, capacitor, diode, resistor, switch, light
3 emitting diode, laser, wiring structure, or interconnect
4 structure.

1 41. A method of fabricating a stack or trench capacitor
2 structure composed of a bottom electrode, a dielectric
3 layer, a top electrode layer and an optional dielectric
4 buffer layer over said capacitor which is connected to
5 underlying circuitry via a plug and optional barrier
6 wherein at least one component of the capacitor structure
7 is deposited according to Claim 24.

1 42. The method of Claim 41 wherein the optional
2 dielectric barrier is selected from the group consisting
3 of SiO_2 , SiO_xN_y , Si_3N_4 , TiON, AlN, SiN, TiN, Ta_2O_5 , TiO_2 ,
4 ZrO_2 , HfO_2 , Al_2O_3 , La_2O_3 , Y_2O_3 , alloys, mixtures or layers
5 thereof, and multicomponent metal oxides.

1 43. The method of Claim 41 wherein the dielectric is a
2 ferroelectric material.

1 44. The method of Claim 41 wherein the plug material is
2 selected from the group consisting of polysilicon, W, Mo,
3 Ti, Cr, Cu, and doped or undoped alloys, mixtures and
4 multilayers thereof.

1 45. The method of Claim 41 wherein the conductive barrier
2 is selected from the group consisting of TaN, TaSiN,
3 TiAlN, TiSiN, TaSiN, TaWN, TiWN, TaSiN, TaAlN, NbN, ZrN,
4 TaTiN, TiSiN, TiAlN, IrO_x, Os, OsO_x, MoSi, TiSi, ReO₂, and
5 doped or undoped alloys, mixtures and multilayers thereof.

1 46. The method of Claim 41 wherein the bottom electrode
2 is selected from the group consisting of conductive
3 materials, polysilicon, Ni, Pd, Pt, Cu, Ag, Au, Ru, Ir,
4 Rh, OsO_x, TaN, TaSiN, Ta, SrRuO₃, LaSrCoO₃, and doped or
5 undoped alloys, mixtures and multilayers thereof.

1 47. The method of Claim 41 wherein the dielectric
2 material is selected from the group consisting of SiO₂,
3 SiO_xN_y, Si₃N₄, Ta₂O₅, TiO₂, ZrO₂, HfO₂, Al₂O₃, La₂O₃, Y₂O₃,
4 multicomponent metal oxides, perovskite type oxide having
5 the formula ABO₃, wherein B is at least one acid oxide
6 containing a metal selected from the group consisting of
7 Al, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W and Cu, and A is at
8 least one additional cation having a positive formal
9 charge of from about 1 to about 3, barium strontium
10 titanate, barium strontium zirconate, barium strontium
11 hafnate, lead titanate, yttrium aluminate, lanthanum
12 aluminate, lead zirconium titanate, strontium bismuth
13 tantalate, strontium bismuth niobate, bismuth titanate,
14 lanthanum silicate, yttrium silicate, hafnium silicate,
15 zirconium silicate, rare earth doped silicates and doped
16 or undoped alloys, mixtures and multilayers thereof.

1 48. The method of Claim 41 wherein the top electrode is
2 selected from the group consisting of polysilicon, Ni, Pd,
3 Pt, Cu, Ag, Au, Ru, Ir, Rh, IrO_x, TaN, TaSiN, Ta, SrRuO₃,

4 LaSrCoO₃, and doped or undoped alloys, mixtures and
5 multilayers thereof.

1 49. A method of fabricating a wiring structure composed
2 of etched trenches and vias into a dielectric layer,
3 optional barrier material between dielectric and wiring
4 material, and wiring material wherein at least one
5 component of the wiring structure is deposited according
6 to Claim 24.

1 50. The method of Claim 49 wherein the dielectric layer
2 is selected from the group consisting of SiO₂, SiO_xN_y,
3 Si₃N₄, phosphosilicate glass, metal oxides, Al₂O₃ and doped
4 or undoped alloys, mixtures and multilayers thereof.

1 51. The method of Claim 49 wherein the optional barrier
2 material is selected from the group consisting of WN, TiN,
3 TaN, SiO₂, SiO_xN_y, Si₃N₄, phosphosilicate glass, metal
4 oxides, Al₂O₃, and doped or undoped alloys, mixtures and
5 multilayers thereof.

1 52. The method of Claim 49 wherein the wiring material is
2 selected from the group consisting of polysilicon, Al, W,
3 Mo, Ti, Cr, Cu and doped or undoped alloys, mixtures and
4 multilayers thereof.

1 53. A method of fabricating an electronic device composed
2 of a substrate having source and drain regions and a
3 channel region between said source and drain regions, a
4 gate dielectric, aligned to and on top of said channel
5 region, and a gate electrode aligned to and on top of said

6 gate dielectric wherein at least one component of the
7 electronic device is deposited according to Claim 24.

1 53. A method of Claim 53 wherein the gate dielectric
2 selected from the group consisting of SiO_2 , SiO_xN_y , Si_3N_4 ,
3 Ta_2O_5 , TiO_2 , ZrO_2 , HfO_2 , Al_2O_3 , La_2O_3 , Y_2O_3 , multicomponent
4 metal oxides, perovskite type oxide having the formula
5 ABO_3 wherein B is at least one acid oxide containing a
6 metal selected from the group consisting of Al, Ti, Zr,
7 Hf, V, Nb, Ta, Cr, Mo, W and Cu, and A is at least one
8 additional cation having a positive formal charge of from
9 about 1 to about 3, barium strontium titanate, barium
10 strontium zirconate, barium strontium hafnate, lead
11 titanate, yttrium aluminate, lanthanum aluminate, lead
12 zirconium titanate, strontium bismuth tantalate, strontium
13 bismuth niobate, bismuth titanate, lanthanum silicate,
14 yttrium silicate, hafnium silicate, zirconium silicate,
15 rare earth doped silicates and doped or undoped alloys,
16 mixtures and multilayers thereof.

1 55. The method of Claim 53 wherein gate dielectric is
2 composed of more than one layer.

1 56. The method of Claim 53 wherein the gate electrode is
2 selected from the group consisting of polysilicon, Al, Ag,
3 Bi, Cd, Fe, Ga, Hf, In, Mn, Nb, Y, Zr, Ni, Pt, Be, Ir, Te,
4 Re, Rh, W, Mo, Cr, Fe, Pd, Au, Rh, Ti, Cr, Cu, and doped
5 or undoped alloys, mixtures and multilayers thereof.

PRECURSOR SOURCE MIXTURES, METHODS OF FILM
DEPOSITION, AND FABRICATION OF STRUCTURES

5

ABSTRACT OF THE DISCLOSURE

A precursor source mixture useful for CVD or ALD of a film comprising: at least one precursor composed of an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi, to which is bound at least one ligand selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and halogenated, sulfonated or silylated derivatives thereof, which is dissolved, emulsified or suspended in an inert liquid selected from the group consisting of aliphatic hydrocarbons, aromatic hydrocarbons, alcohols, ethers, aldehydes, ketones, acids, phenols, esters, amines, alkynitrile, halogenated hydrocarbons, silylated hydrocarbons, thioethers, amines, cyanates, isocyanates, thiocyanates, silicone oils, nitroalkyl, alkynitrate, and mixtures thereof. The precursor source mixture may be a solution, emulsion or suspension and may consist of a mixture of solid, liquid and gas phases which are distributed throughout the mixture.

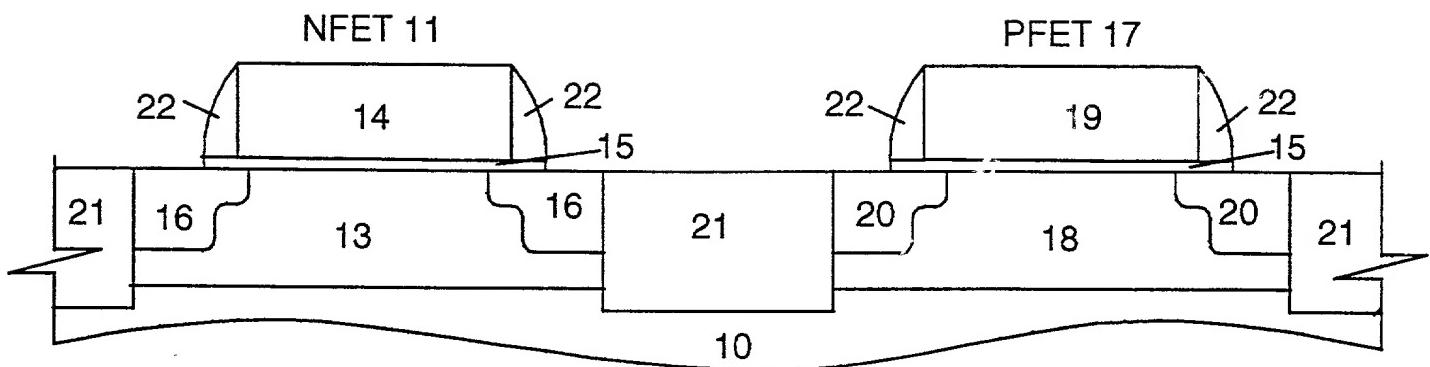


FIG 1

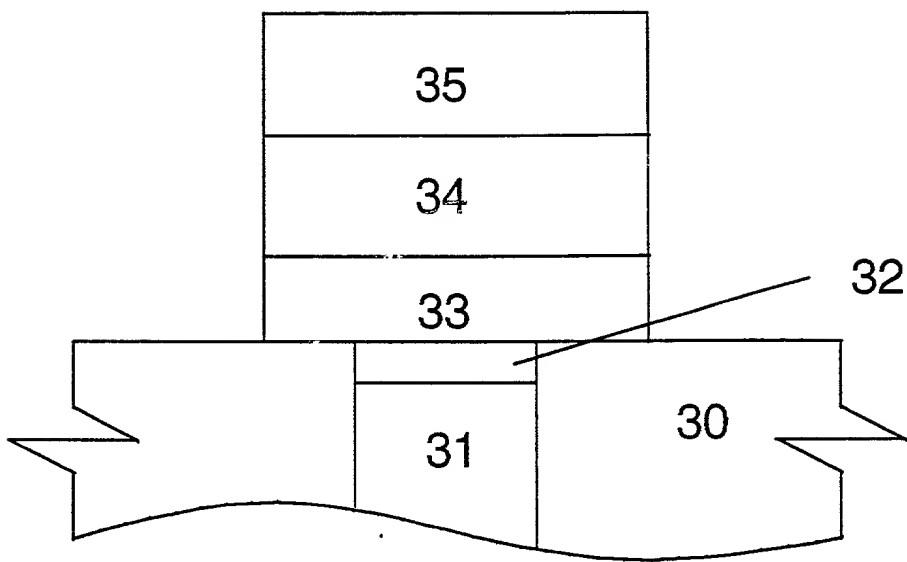


FIG 2

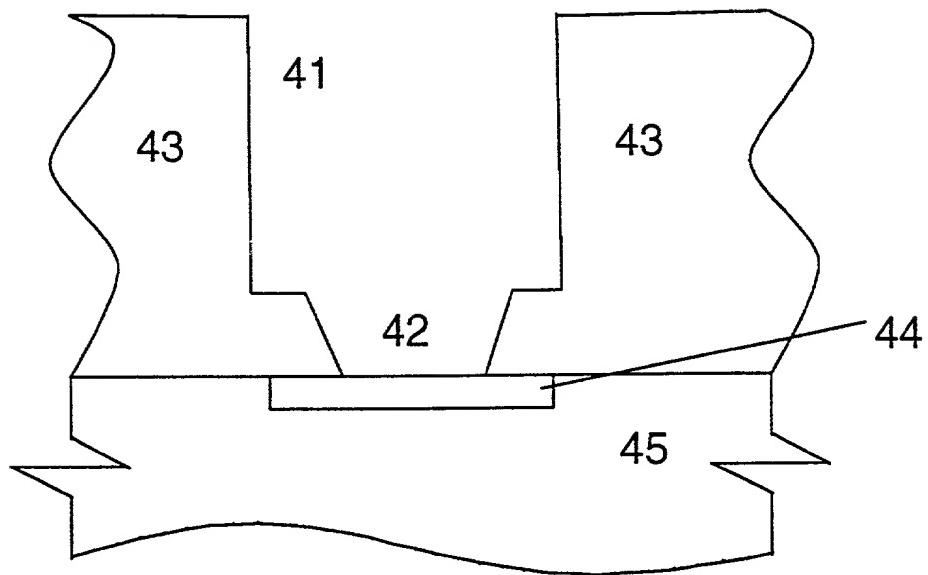


FIG 3a

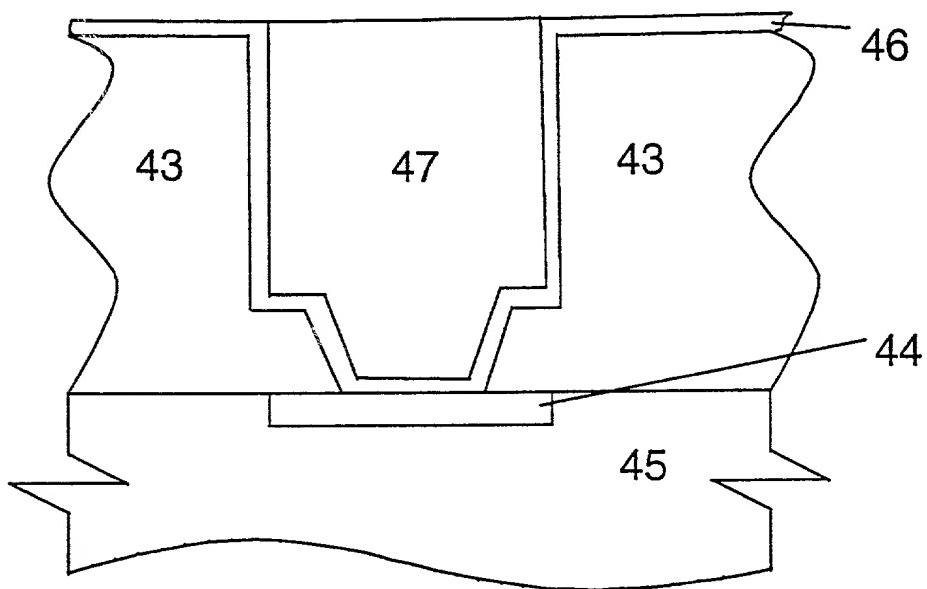


FIG 3b

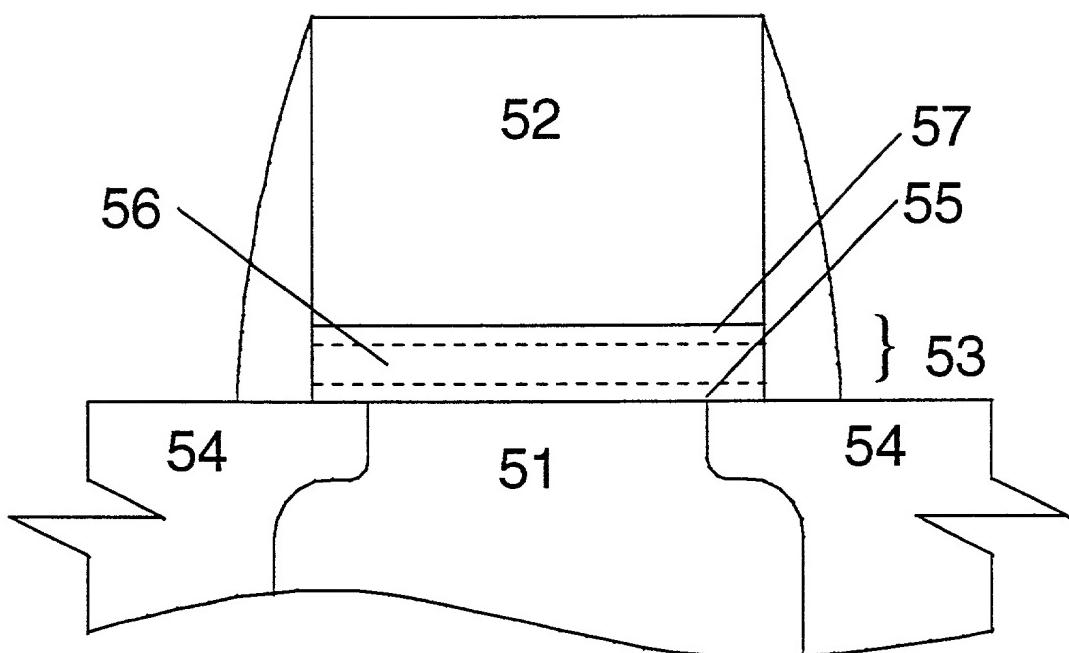


FIG 4

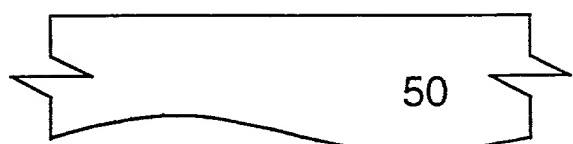


Fig. 5

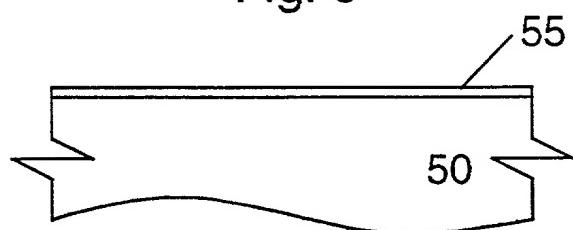


Fig. 6

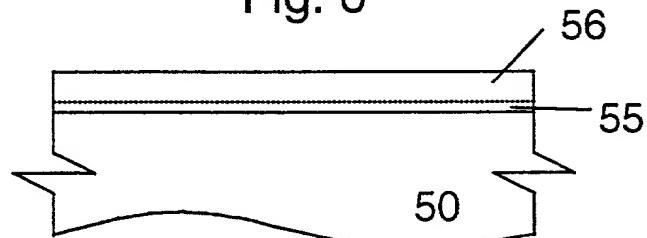


Fig. 7

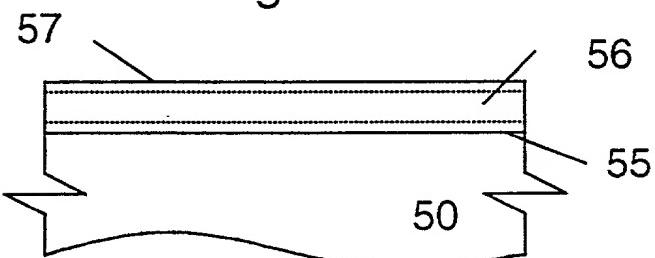


Fig. 8

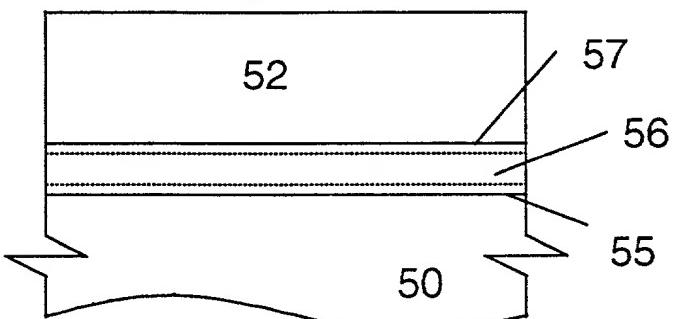


Fig. 9

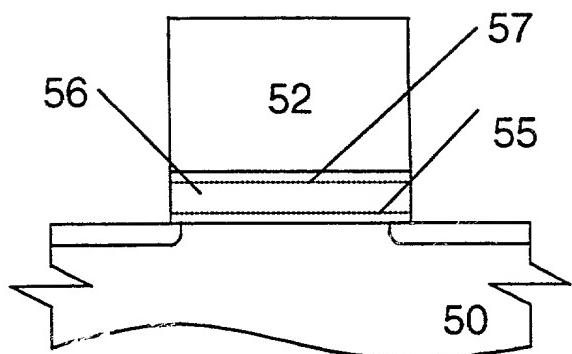


Fig. 10

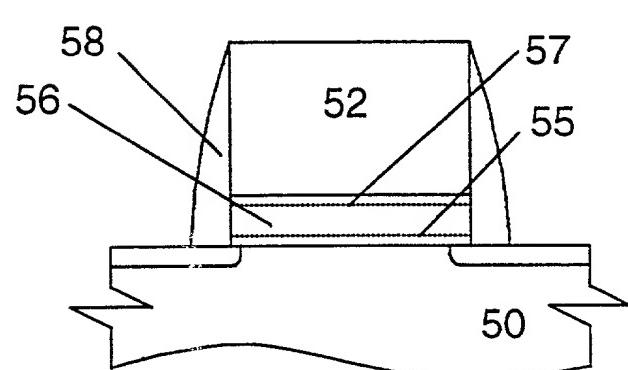


Fig. 11

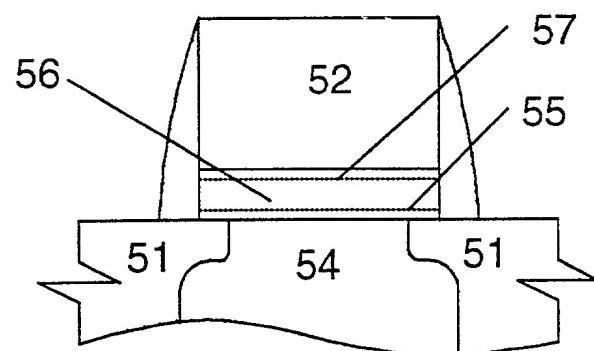


Fig. 12

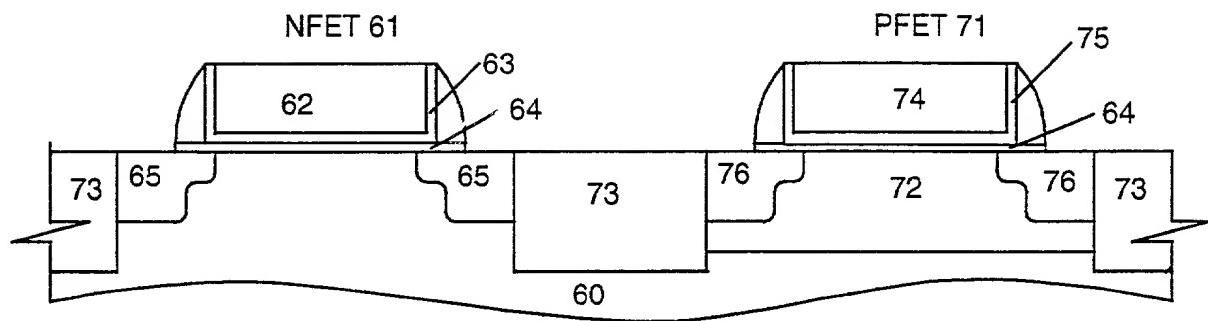


Fig. 13

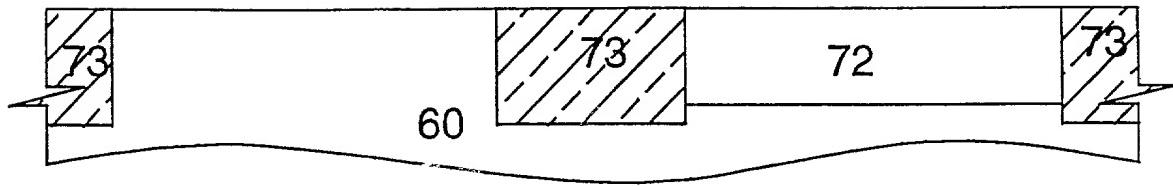


Fig. 14

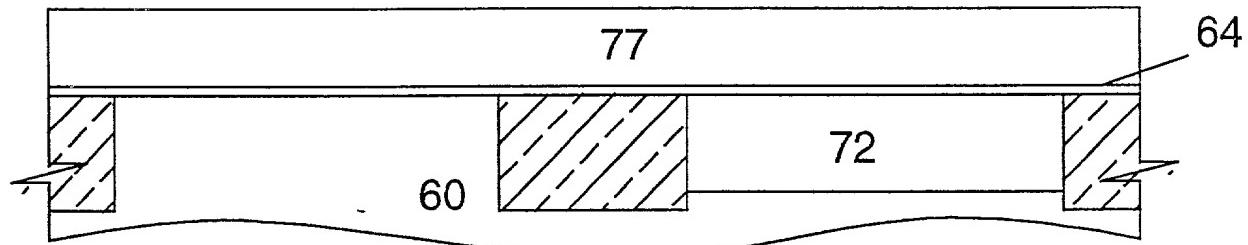


Fig. 15

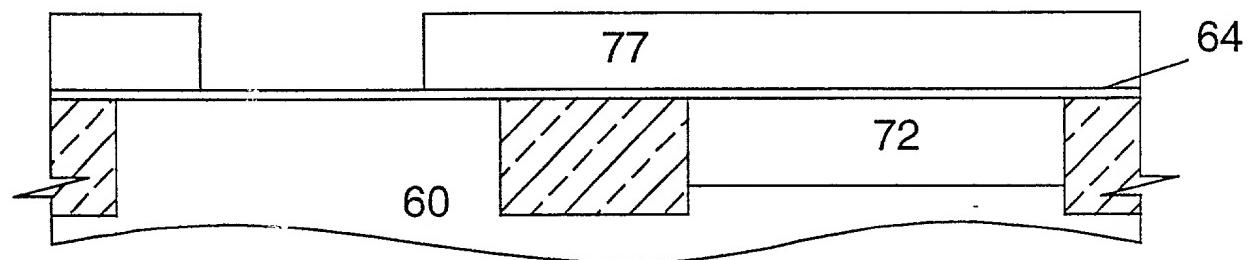


Fig. 16

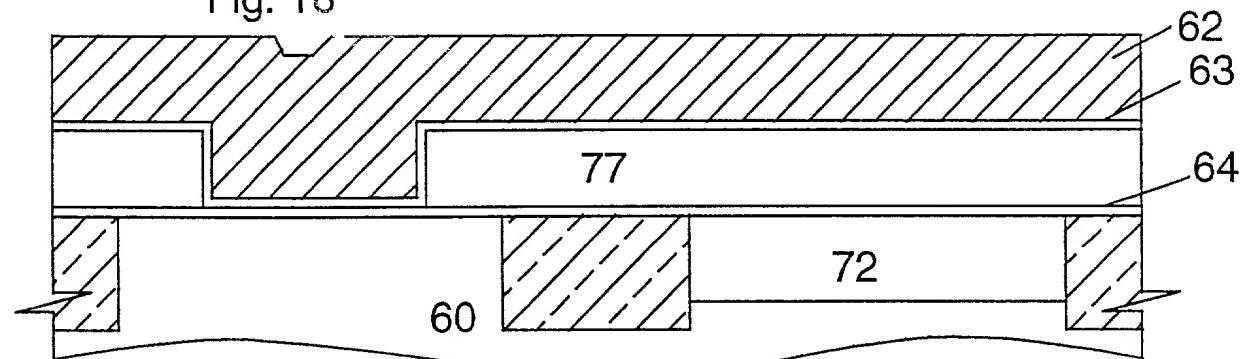


Fig. 17

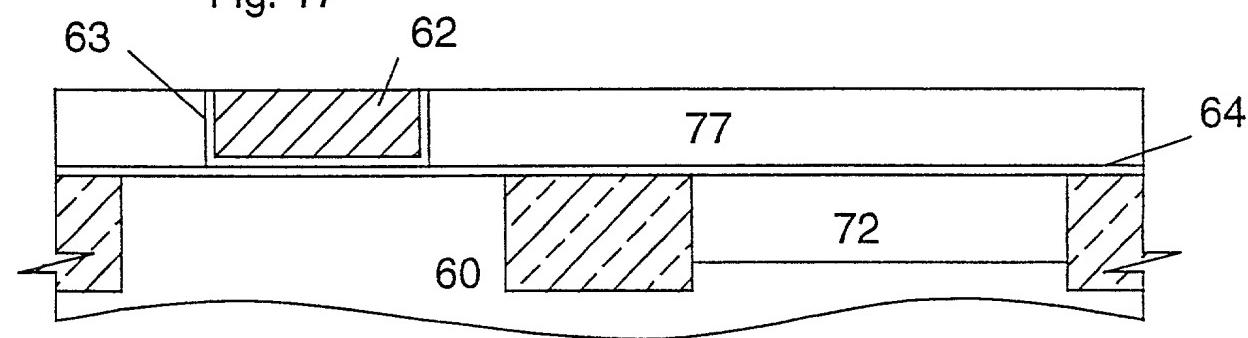


Fig. 18

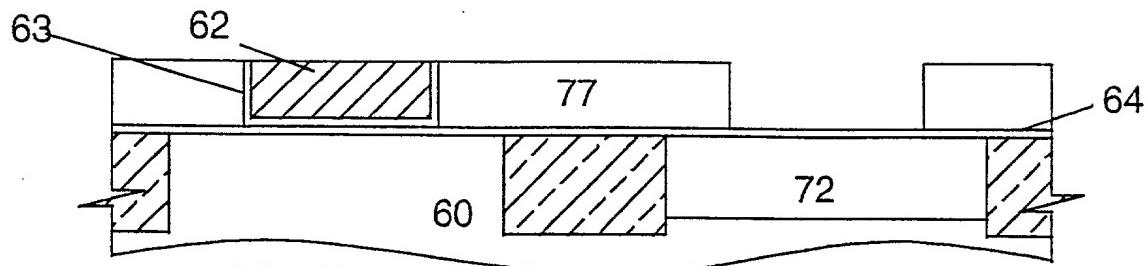


Fig. 19

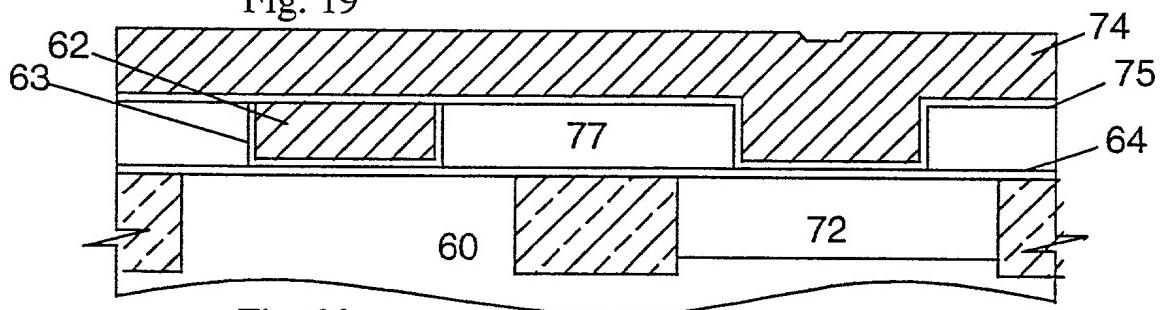


Fig. 20

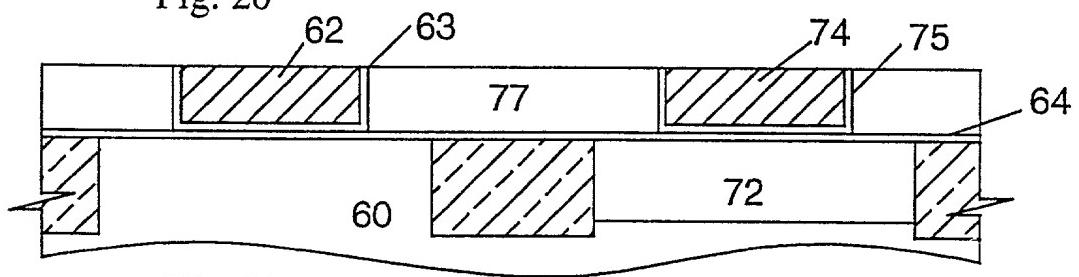


Fig. 21

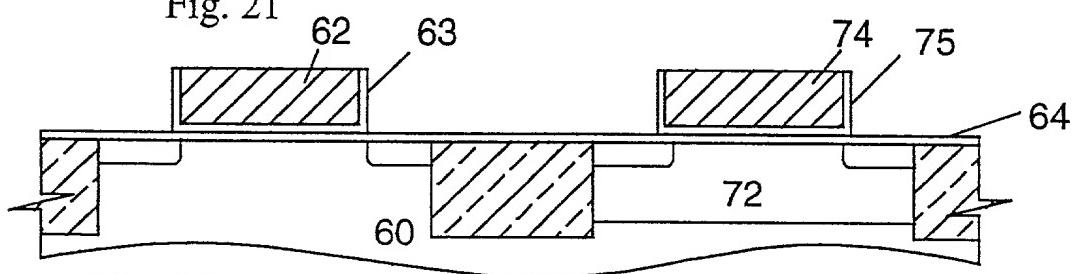


Fig. 22

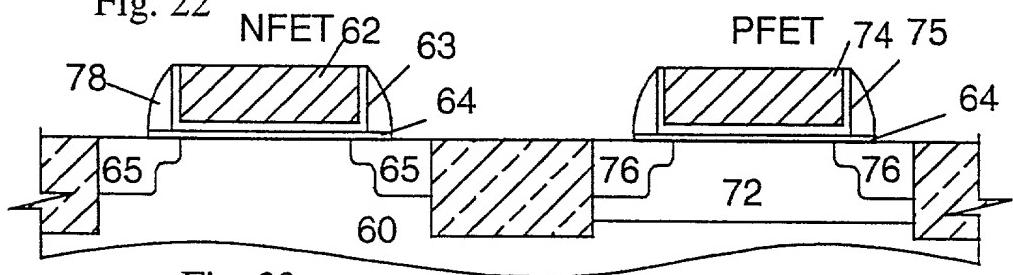


Fig. 23

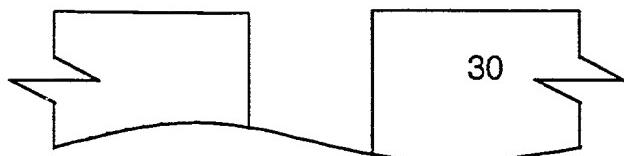


FIG 24

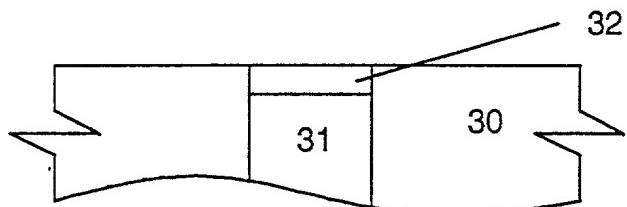


FIG 25

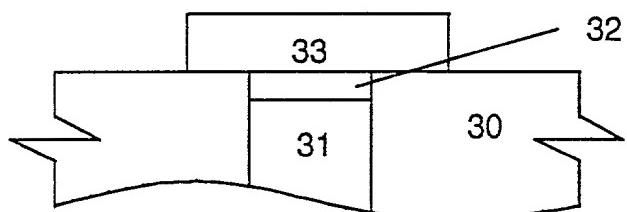


FIG 26

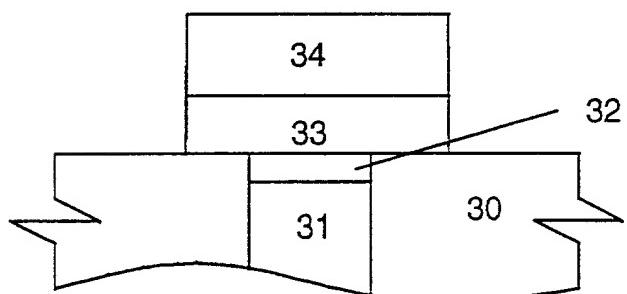


FIG 27

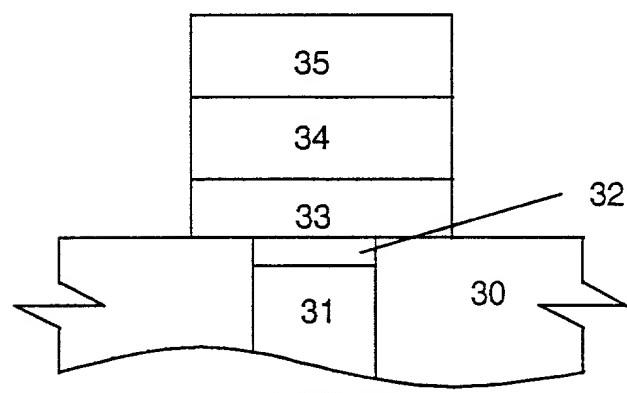


FIG 28

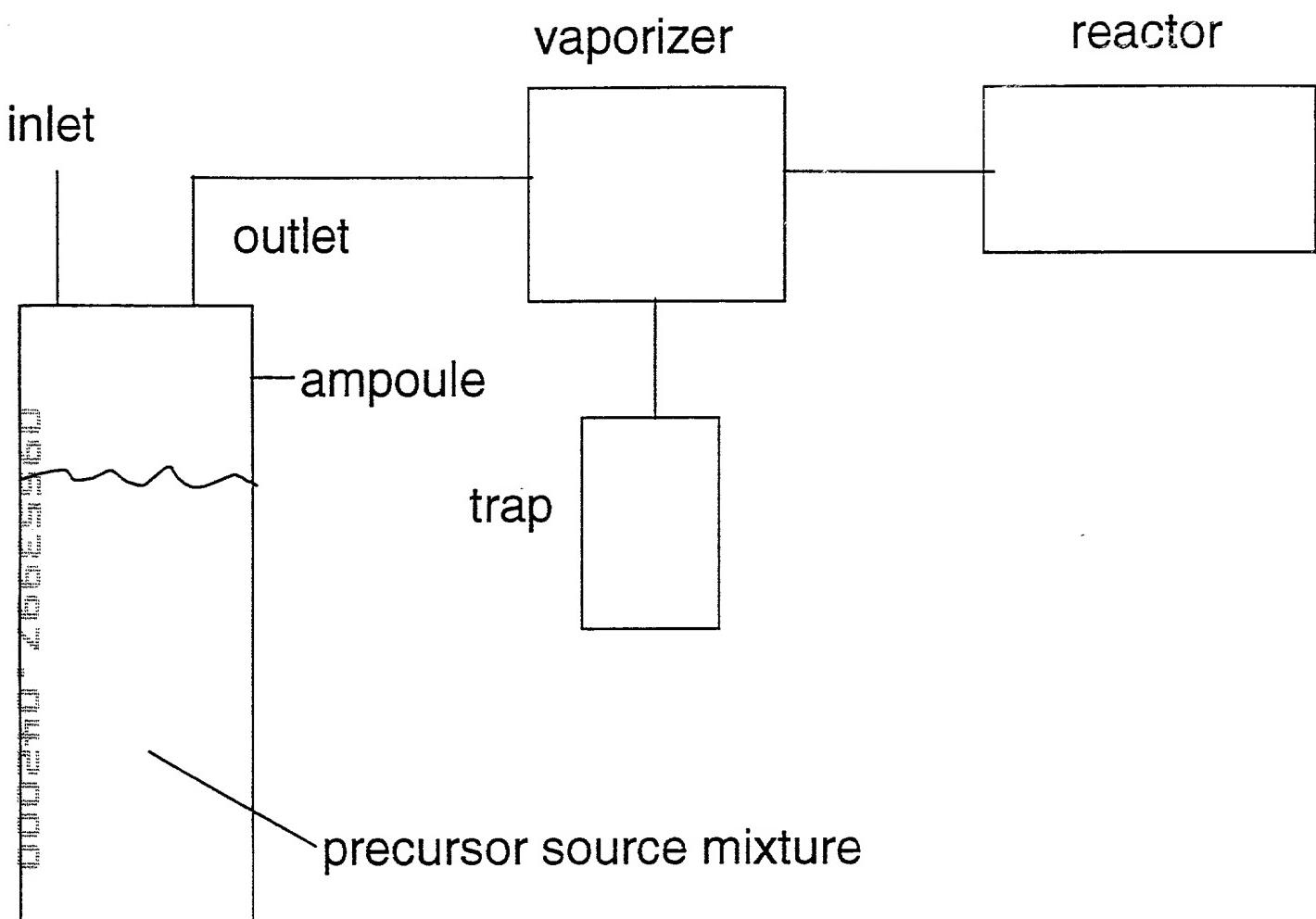


Fig. 29

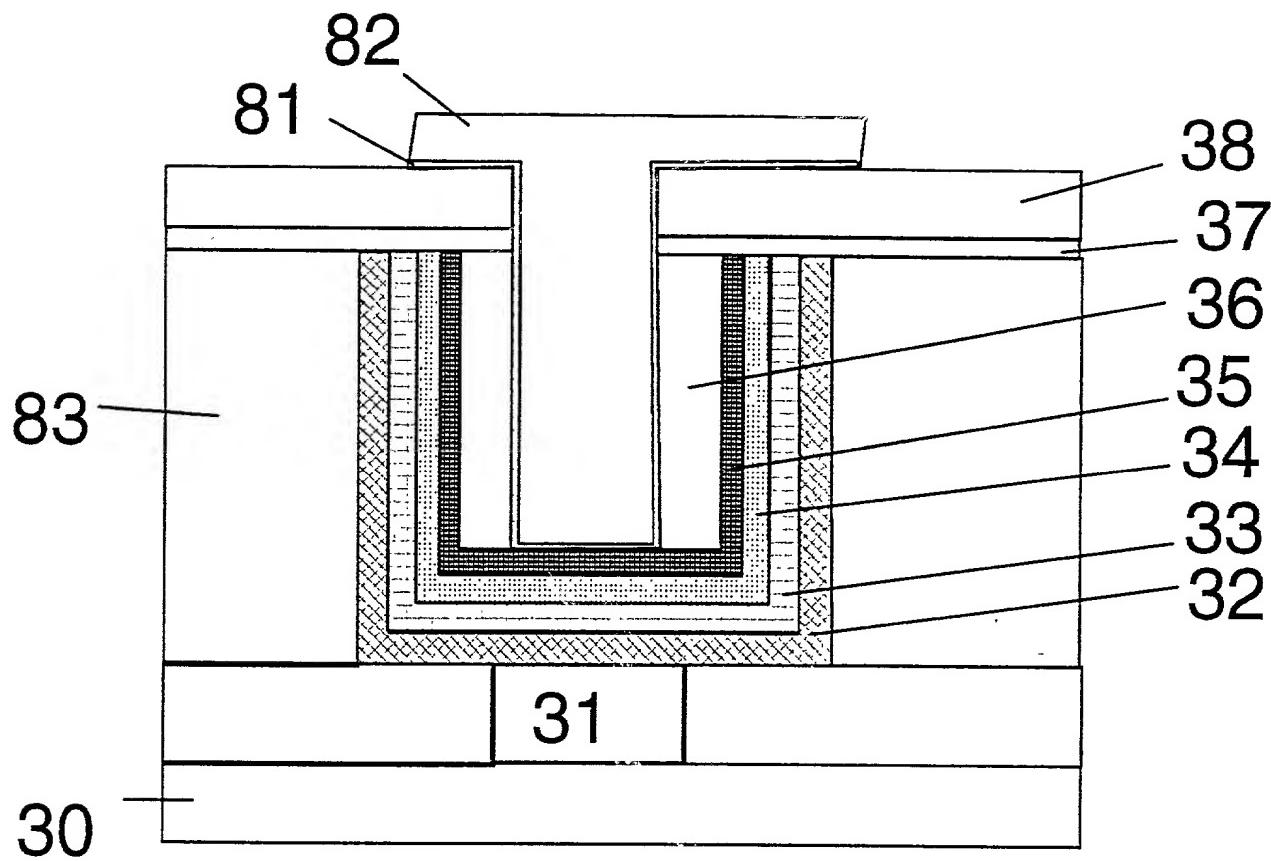


FIG 30

DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: PRECURSOR SOURCE MIXTURES, METHODS OF FILM DEPOSITION, AND FABRICATION OF STRUCTURES

the specification of which (check one)

is attached hereto.

— was filed on — as United States Application Number —

or PCT International Application Number —

and was amended on — (if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119(a)-(d) or §365(b) of any foreign application(s) for patent or inventor's certificate, or §365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application, having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

			Priority Claimed
(Number)	(Country)	(Day/Month/Year Filed)	Yes No

I hereby claim the benefit under 35 U.S.C. §119(e) of any United States provisional application(s) listed below.

(Application Number)	(Filing Date)

I hereby claim the benefit under 35 U.S.C. §120 of any United States Application(s), or §365(c) of any PCT International application designating the United States, listed below, and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States, or PCT International application in the manner provided by the first paragraph of 35 U.S.C. §112, I acknowledge the duty to disclose information material to the patentability of this application as defined in 37 CFR §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As a named inventor I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith (list name and registration number).

Manny W. Schecter (Reg. 31,722), Terry J. Ilardi (Reg. 29,936), Christopher A. Hughes (Reg. 26,914), Edward A. Pennington (Reg. 32,588), John E. Hoel (Reg. 26,279), Joseph C. Redmond, Jr. (Reg. 18,753), Douglas W. Cameron (Reg. No. 31,596), Wayne L. Ellenbogen (Reg. No. 43,602), Stephen C. Kaufman (Reg. No. 29,551), Daniel P. Morris (Reg. No. 32,053), Louis J. Percello (Reg. No. 33,206), Jay P. Sbrollini (Reg. No. 36,266), David M. Shofri (Reg. No. 39,835), Robert M. Trepp (Reg. No. 25,933) and Louis P. Herzberg (Reg. No. 41,500).

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